



# CRYOGENIC MODELING AND PROCESS DESIGN KIT FOR A CMOS 28-NM BULK TECHNOLOGY

LUCA CASTELLANI – FEE 2026 PARIS



UNIVERSITÀ  
DI TORINO



21/05/2026

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Integrated  
Computing  
Architectures



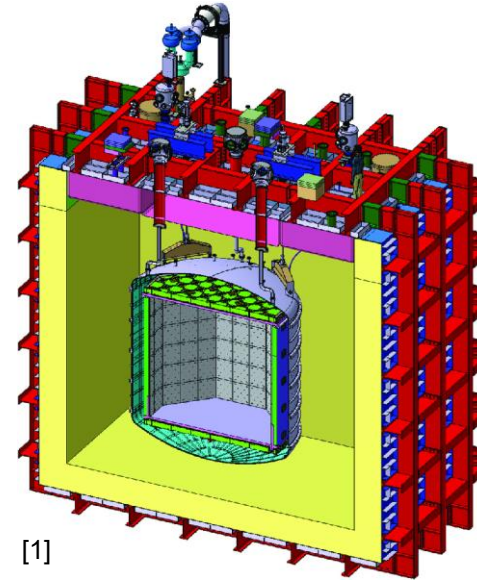
# REASON FOR CRYOGENIC PDK DEVELOPMENT

## Thesis Goal

- Cryogenic ICs → cryogenic particle detectors readout and quantum computing control
- Dark matter/neutrino detectors → scalability  
quantum processors → interconnect
- Si Foundries → **PDK** (Process Design Kits) for a CMOS tech node.  
Valid only down to -40° C
- Cryogenic Designs → custom models

### Goal :

establish a cryo characterization and extraction methodology for a 28nm bulk CMOS technology → partial cryo-PDK



Darkside20k liquid Ar  
cryo-TPC  
in construction  
@LNGS, Italy

Example of fixed cryo-T  
dilution cryostat for  
quantum computing  
prototypes

300 K

70 K

4 K

100 mK

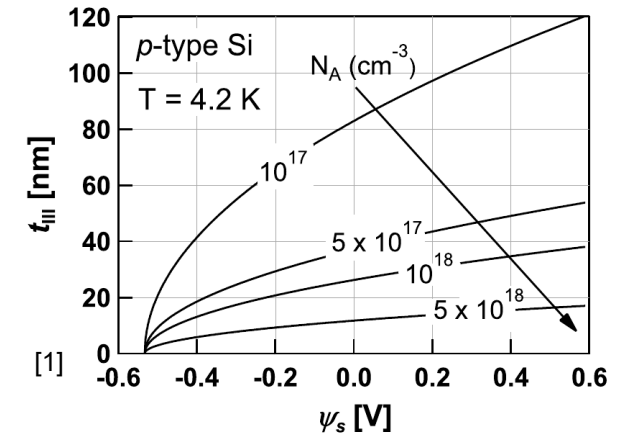
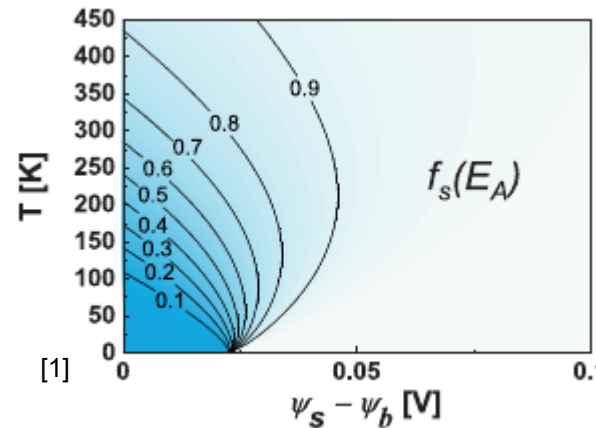
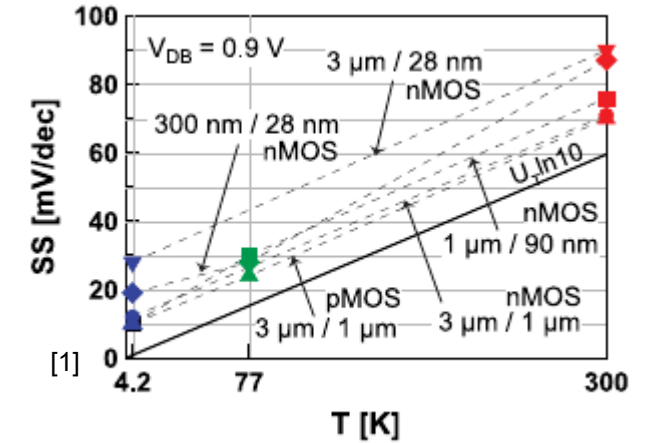
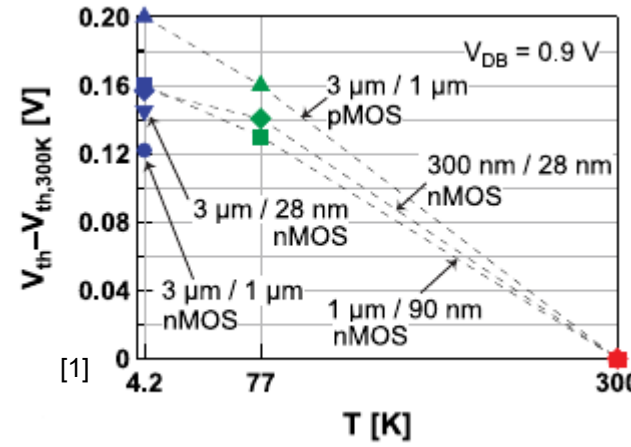
20 mK



[1] DarkSide-20k sensitivity to light dark matter particles, Acerbi et al. 2024

# CRYOGENIC PHENOMENA - CMOS ELECTRONICS

- Threshold voltage  $V_{TH}$  **increases**
- Subthreshold swing ( $SS$ ) **decreases** → slope increases
- Mobility **increases** (phonon scatt. red.)
- Dopant **freeze-out**
- Built-in potentials **increase** → PN junction depletion regions widen
- Thermal noise **reduction**
- (+ short channel effects!)



[1] "Characterization and Modeling of 28 nm Bulk CMOS Technology down to 4.2K" Beckers et al., 2018

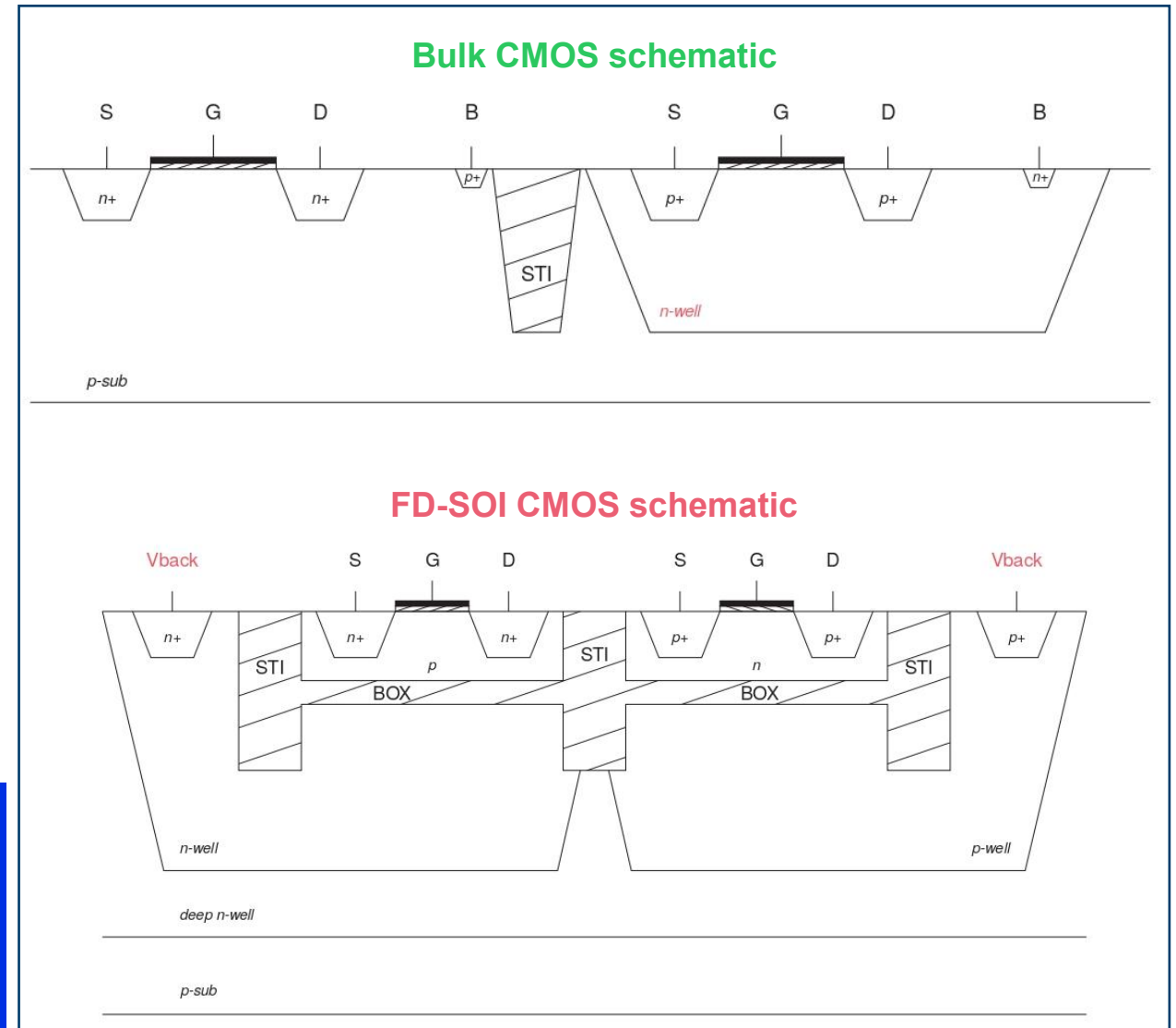
# 28-NM BULK CMOS

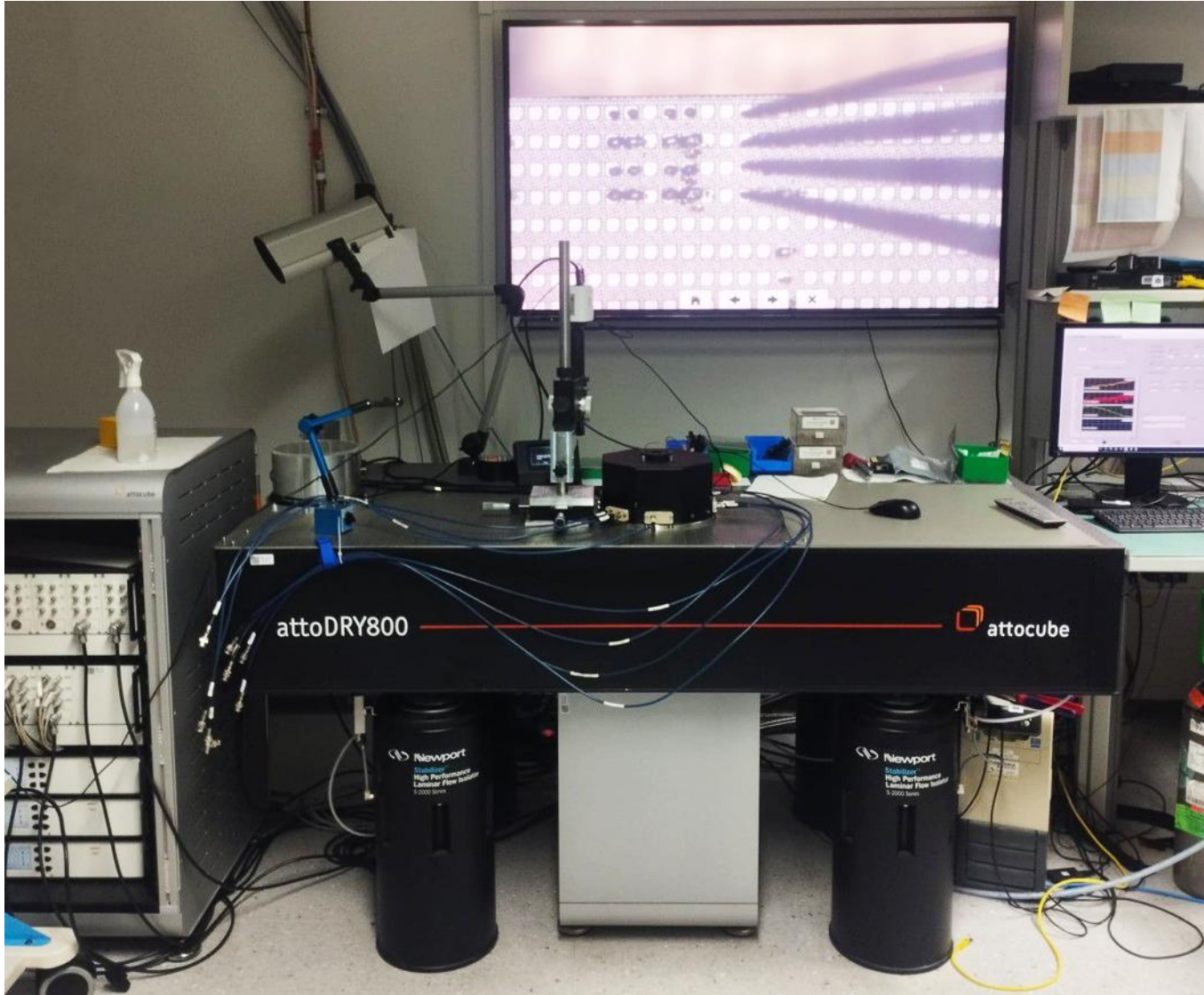
## Technology Overview @cryo T

- Mature commercial tech, 2011
- Balance of **cost**, **power consumption** and **performance**
- Dominant in many applications (Detector ASICs, Analog/Mixed-Signal Ics, scientific R&D)
- One of the last av. planar CMOS nodes

### BULK vs FD-SOI @CRYO:

- Cost effective
- Less self heating
- No  $V_{TH}$  control ( $V_{back}$ )
- Freeze out





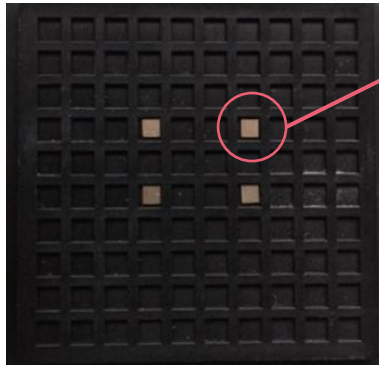
# CRYOGENIC MEASUREMENT SETUP

## FORSCHUNGSZENTRUM JUELICH

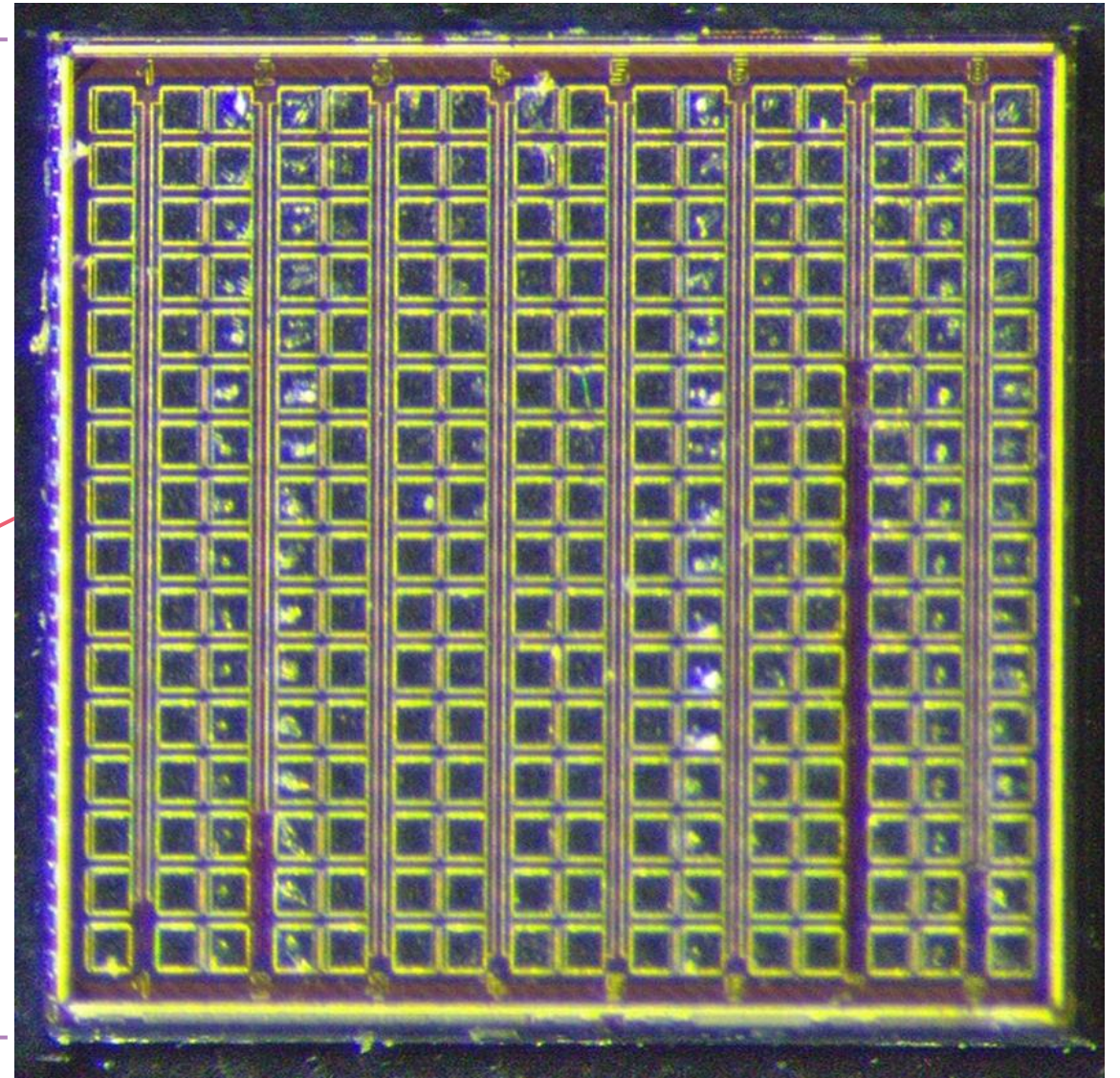
# SAMPLE DUT

## 28-nm CMOS multi-geometry chip for needle probing

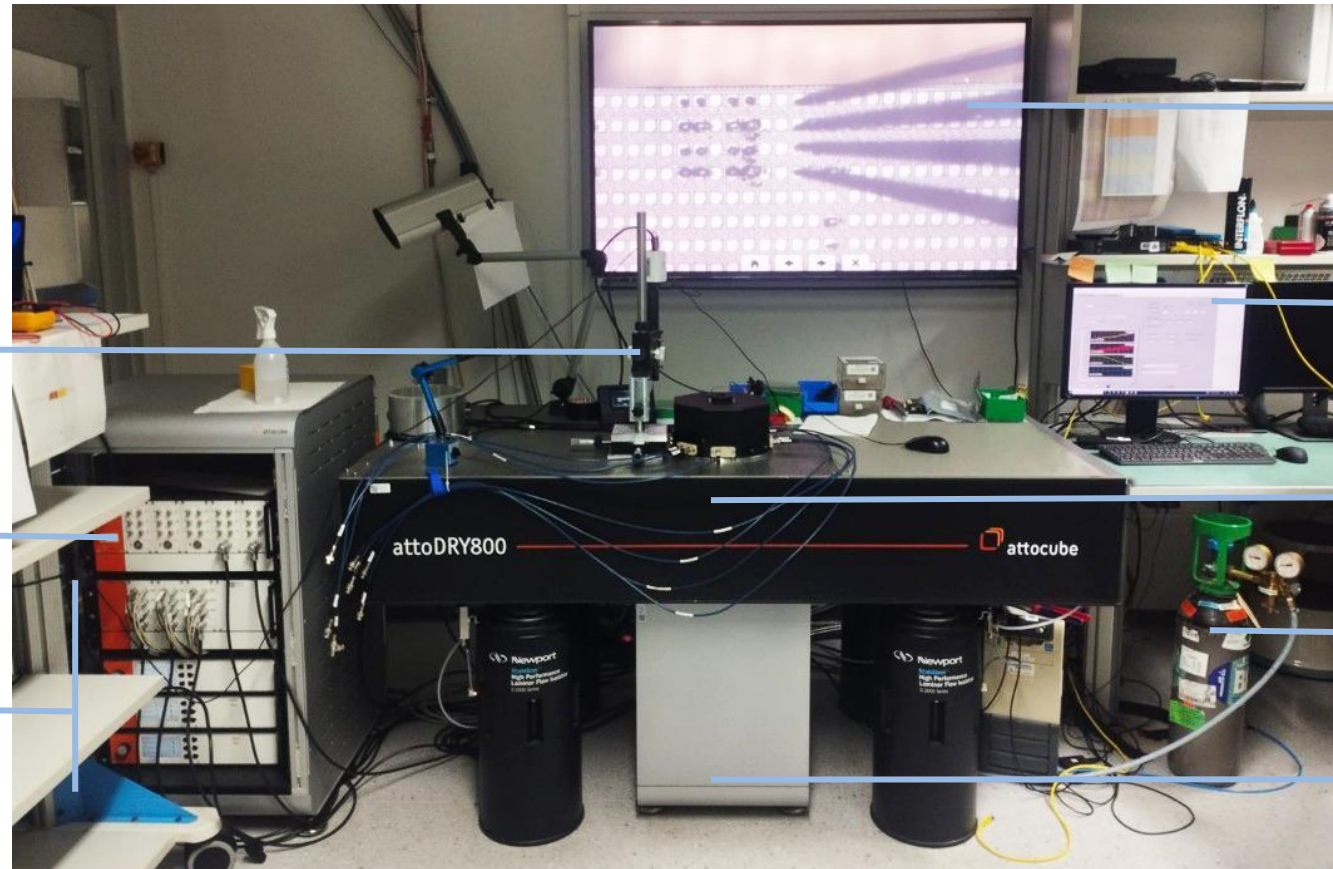
- Courtesy of Giulio Borghello – DRD7, CERN
- pMOS and nMOS Test-transistors on p-sub
- Intended for Total Ionizing Dose (TID) tests
- 28-nm, 16 pads per Column



1 mm



# ATTODRY800 DRY CRYOSTAT WORKSTATION



Microscope

Fischer Lines

Piezo Modules

Probing Screen

Control PC

Cryostat

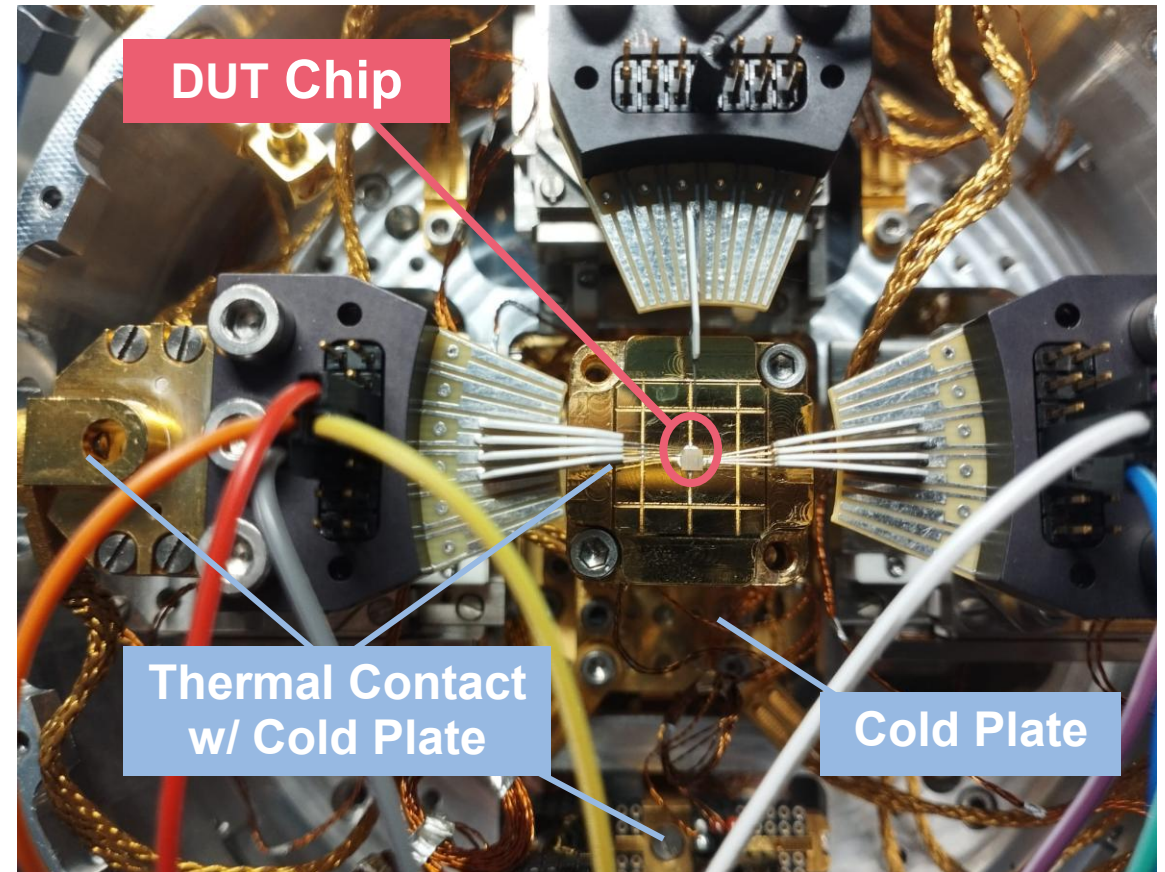
N2 Bottle

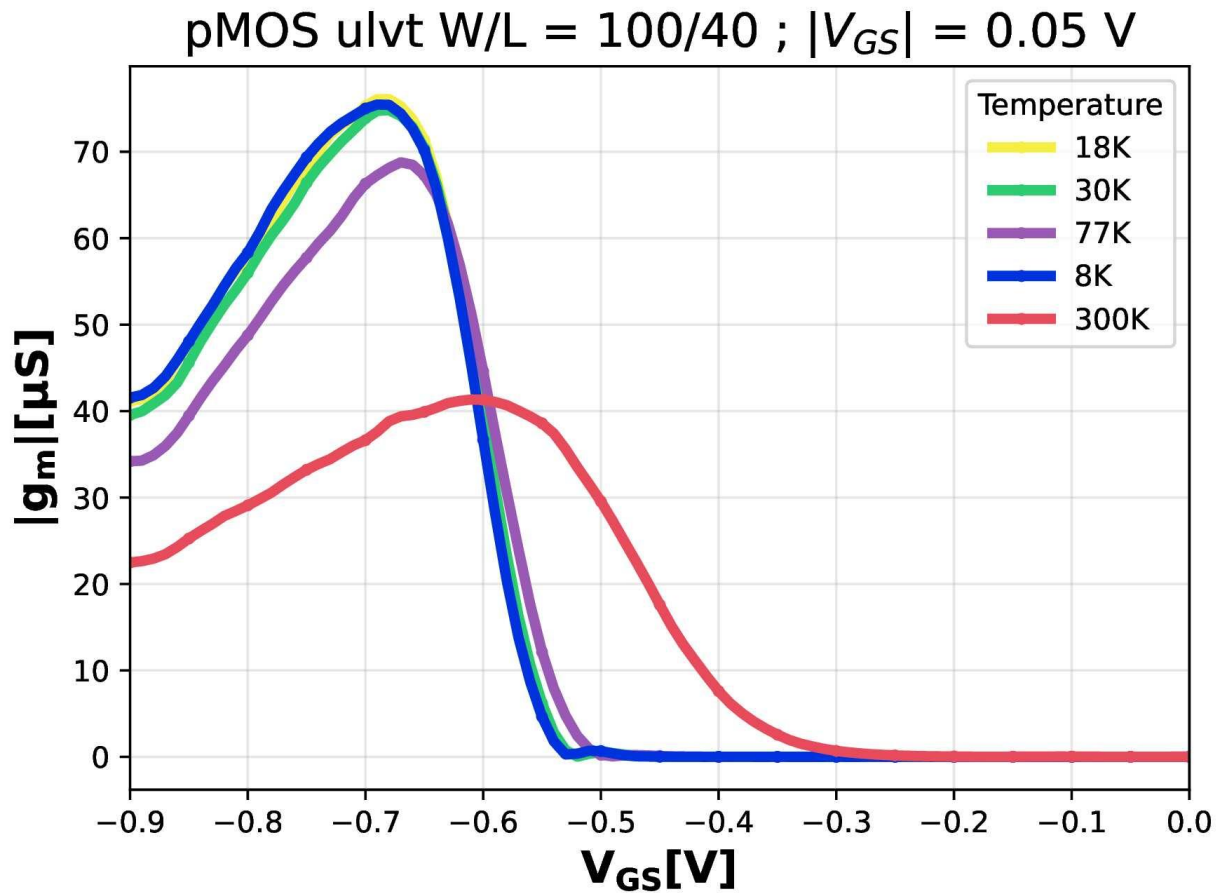
Vacuum Circuit

# ATTODRY800 CRYOSTAT SETUP

## Needle Probing Configuration

- AttoDRY800 dry cryostat @FZJ
- Configuration with 3 **Piezo Positioners**, mounting a needle probe
- DC signal through **Fischer Lines**
- Outer shield: thermalized at **60K**
- Probes, Fischer slots and sample chip thermalized @8K
- Heater and T sensor under sample base



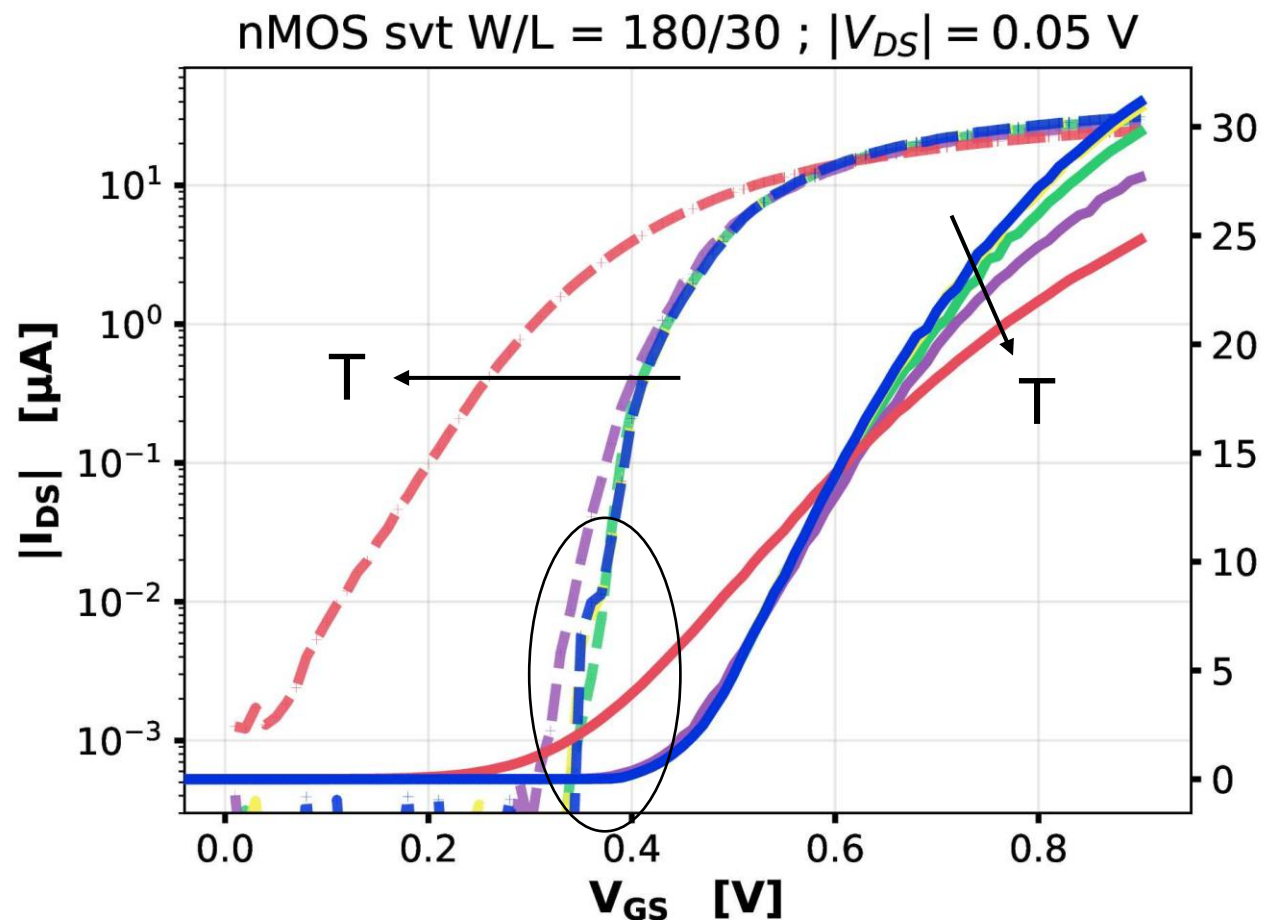


**CRYOGENIC  
TEMPERATURE  
DEPENDENCE  
CHARACTERIZATION**

**FORSCHUNGSZENTRUM  
JUELICH**

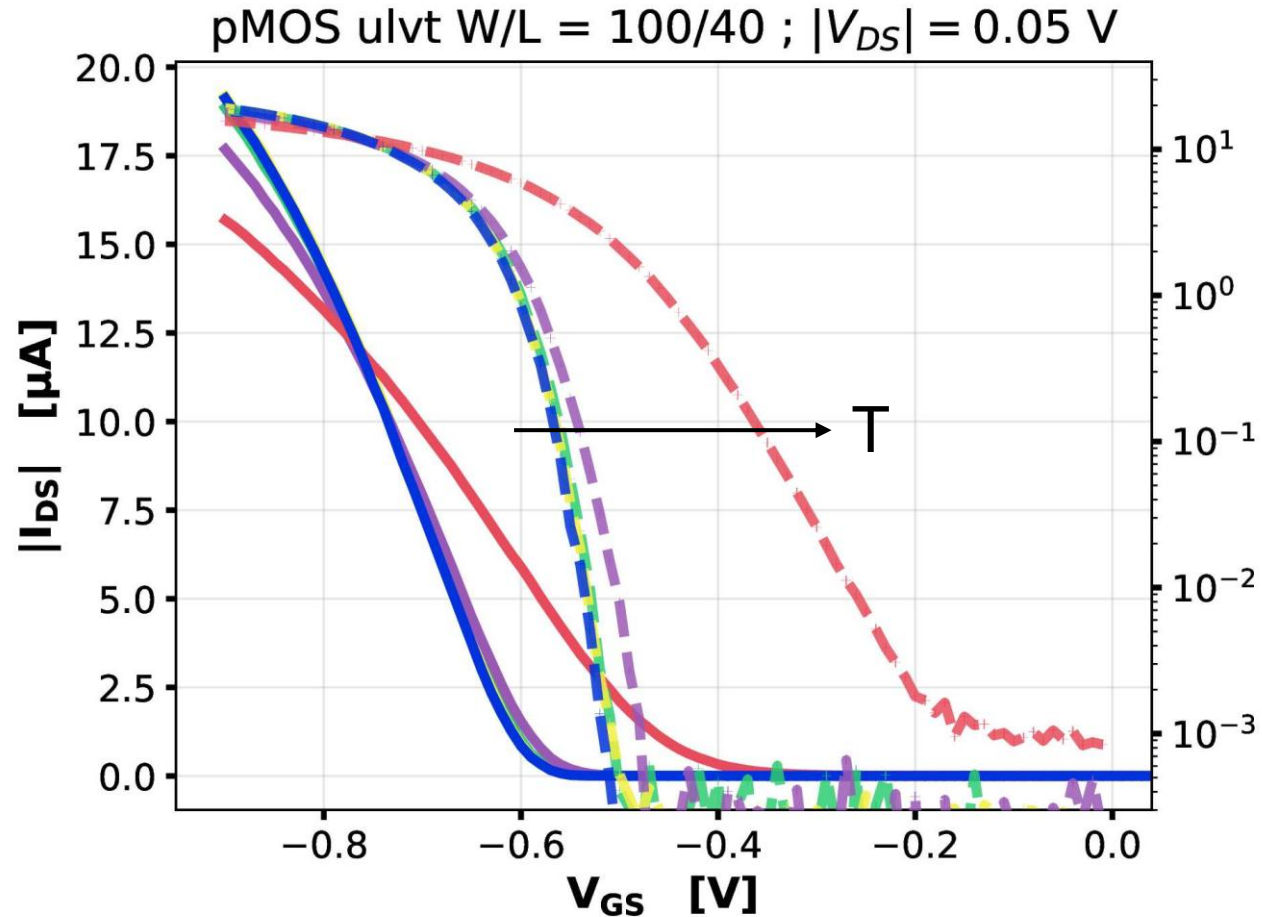
# TRANSFER CURRENTS

- Measured @ **300K**, **77K**, **30K**, **18K**, **8K**
- Different geometries and threshold flavours (svt, lvt, ulvt)
- Example: Standard  $V_{th}$  nMOS 180/30
- Dashed lines – log scale; solid lines – lin scale
- Evident increase of subthreshold slope @ cryo T



# TRANSFER CURRENTS

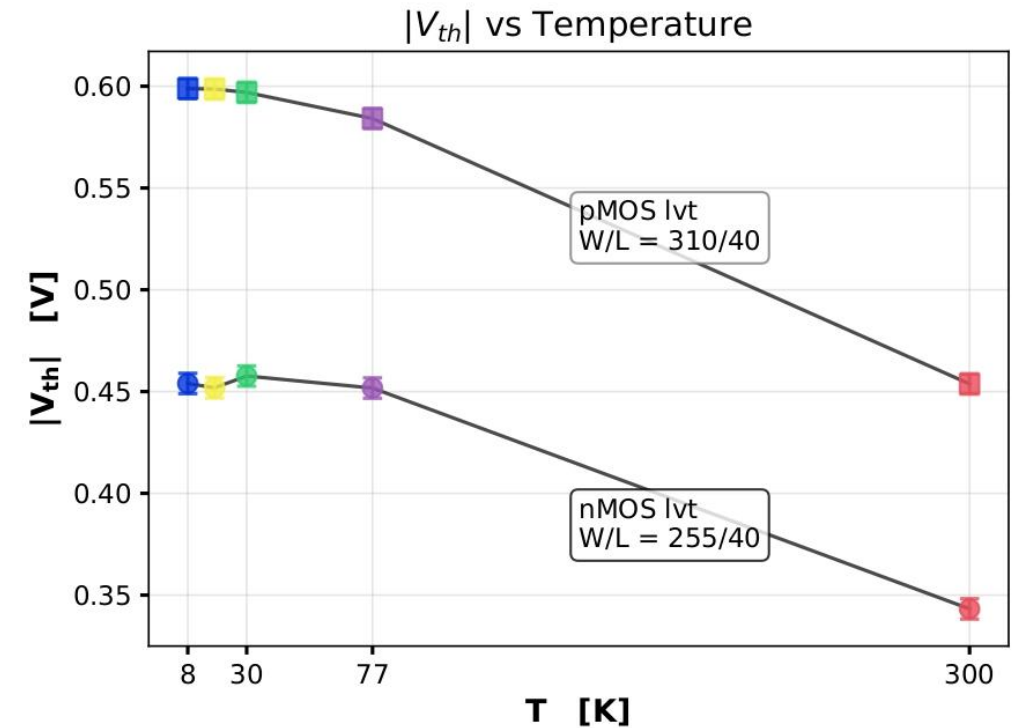
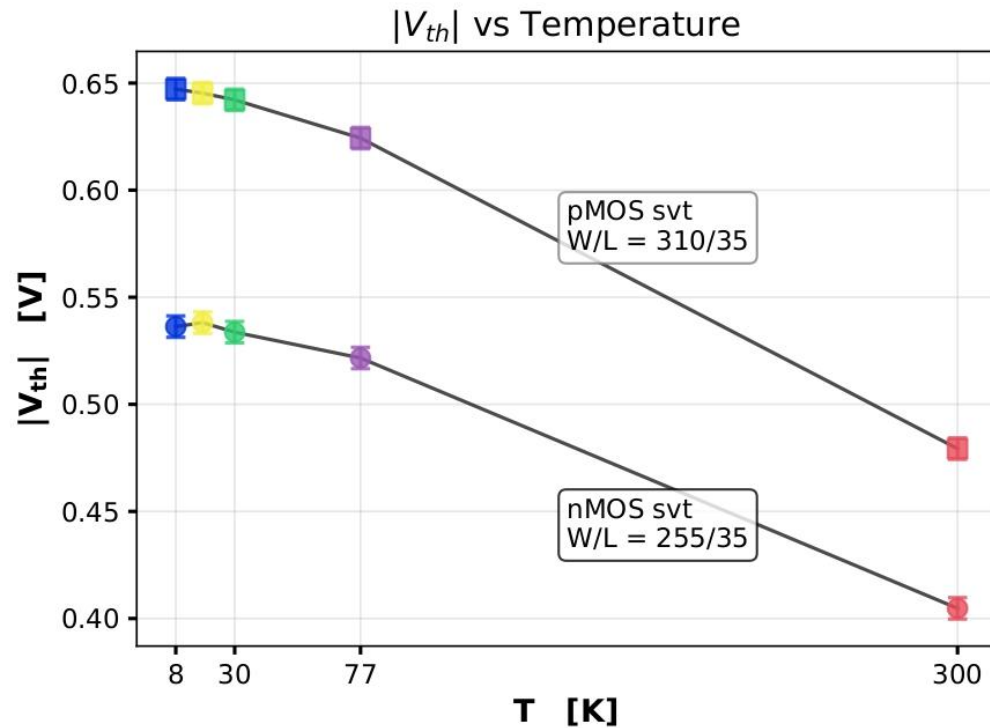
- Measured @ **300K**, **77K**, **30K**, **18K**, **8K**
- Different geometries and threshold flavours (svt, lvt, ulvt)
- Example: Ultra-low  $V_{th}$  pMOS 100/40
- Dashed lines – log scale; solid lines – lin scale
- Evident increase of subthreshold slope @ cryo T



# THRESHOLDS

## LE (Linear Extrapolation) Method <sup>[1]</sup>

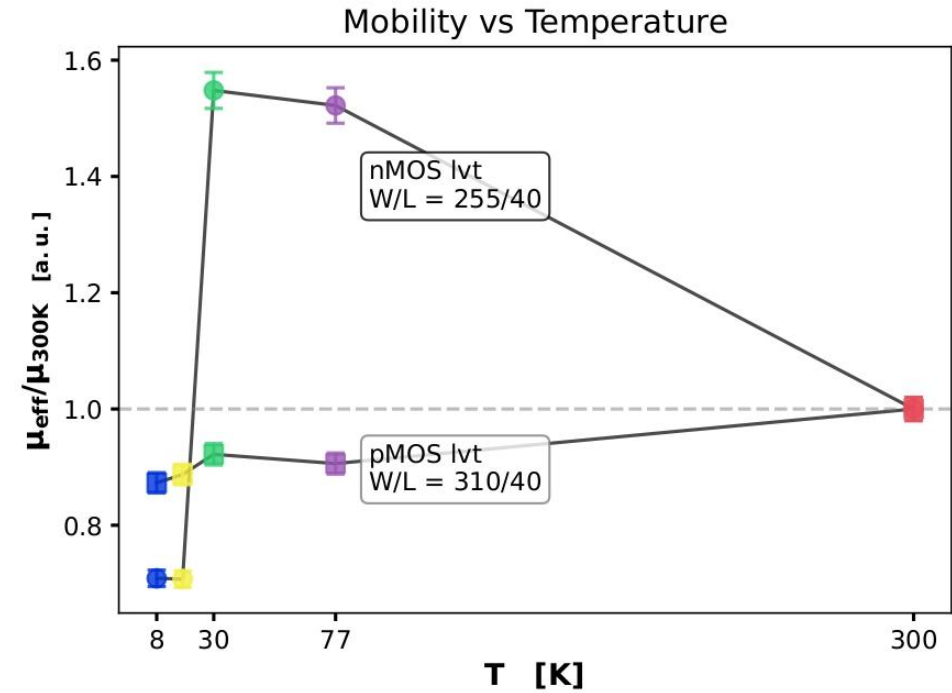
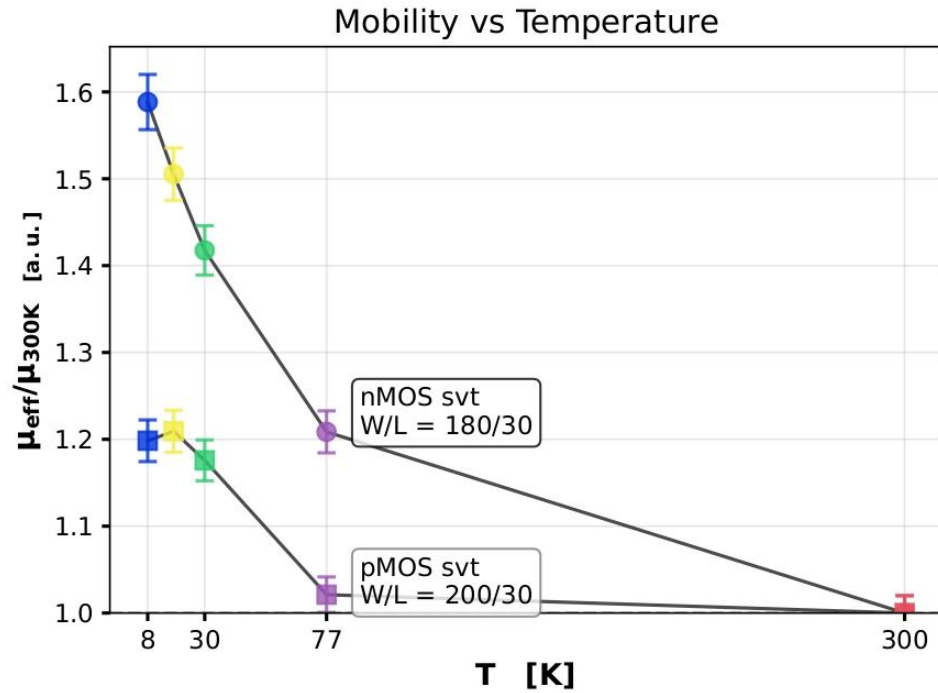
- Threshold increase of more than 100mV @cryo T observed for every device



[1] "Revisiting MOSFET threshold voltage extraction methods" Ortiz-Conde et al., 2013

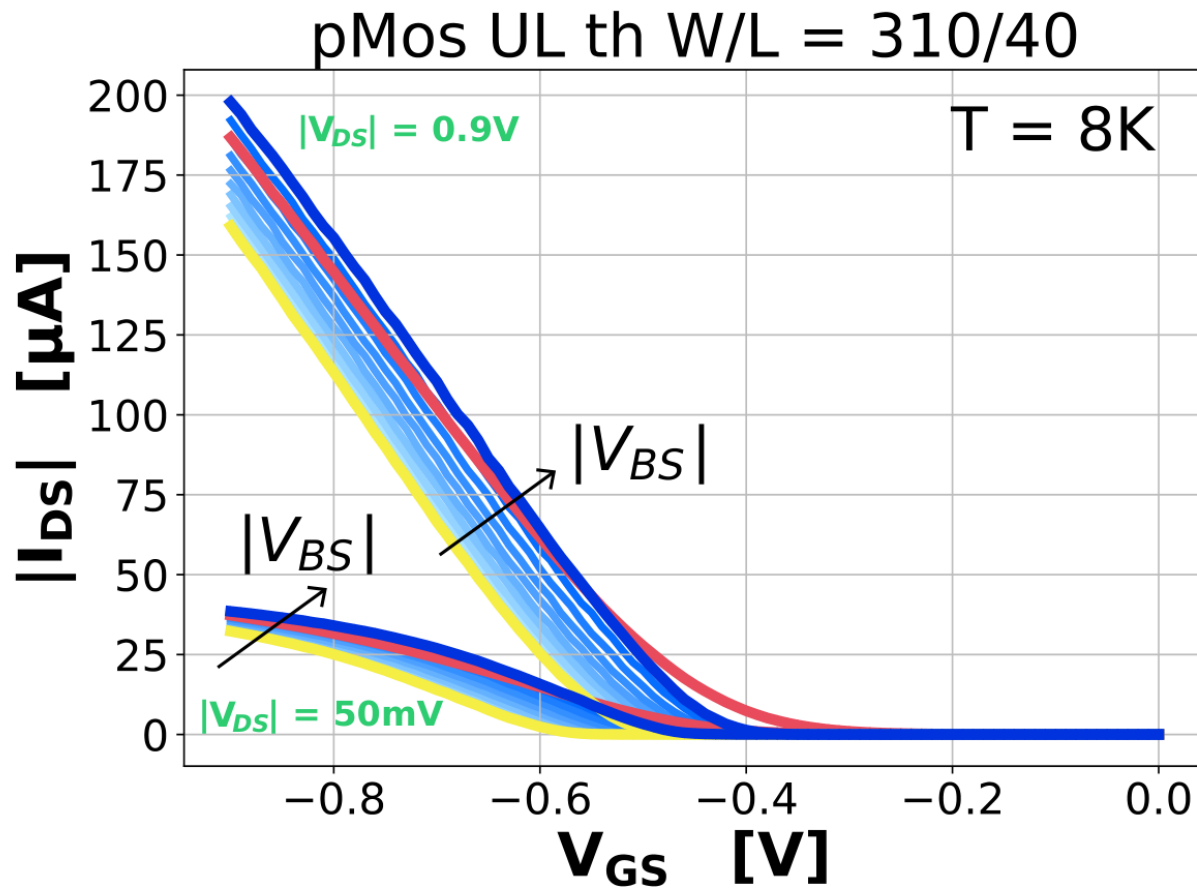
# FREE-CARRIER MOBILITIES

Jazaeri  $g_{ds}$  method <sup>[1]</sup>



- $\mu_{eff} \cong -2 \cdot \frac{L}{W} \cdot \frac{1}{C_{ox}} \cdot \frac{\partial g_{ds}}{\partial V_{DS}}$  where  $C_{ox}$  is the gate-oxide capacitance and  $\frac{\partial g_{ds}}{\partial V_{DS}}$  is fitted at  $|V_{GS}| = 900mV$   
 (strong inversion)  $|V_{DS}| = 50mV$  (linear region)

[1] „Free Carrier Mobility Extraction in FETs”, F. Jazaeri et al., 2017



# THRESHOLD ADJUSTMENT IN BULK TECHNOLOGY

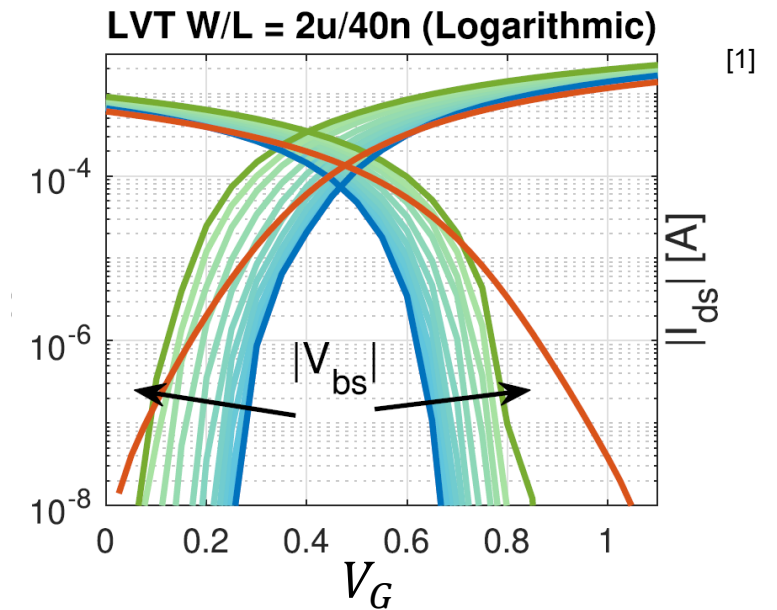
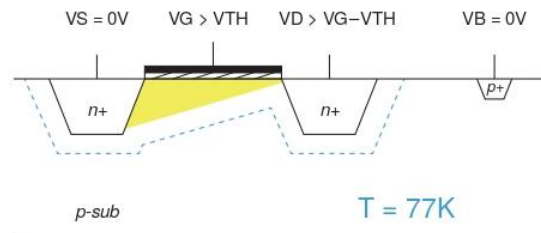
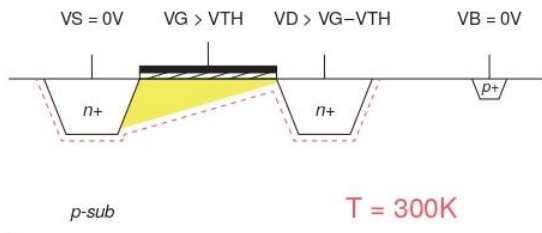
## FORSCHUNGSZENTRUM JUELICH

# FORWARD BODY BIASING FOR TUNING $V_{th}$

- In a Bulk Tech: increasing the Source-Bulk potential: Forward body biasing (FBB) → Compensation of  $V_{th}$  (bigger tech nodes)

$$V_{th,n/p} \propto \sqrt{V_{SB}}$$

- Demonstrated in 40 nm Tech → possible because of increasing built-in potentials and depletion regions at cryo T [1]
- First time test on 28-nm, only pMOS FBB



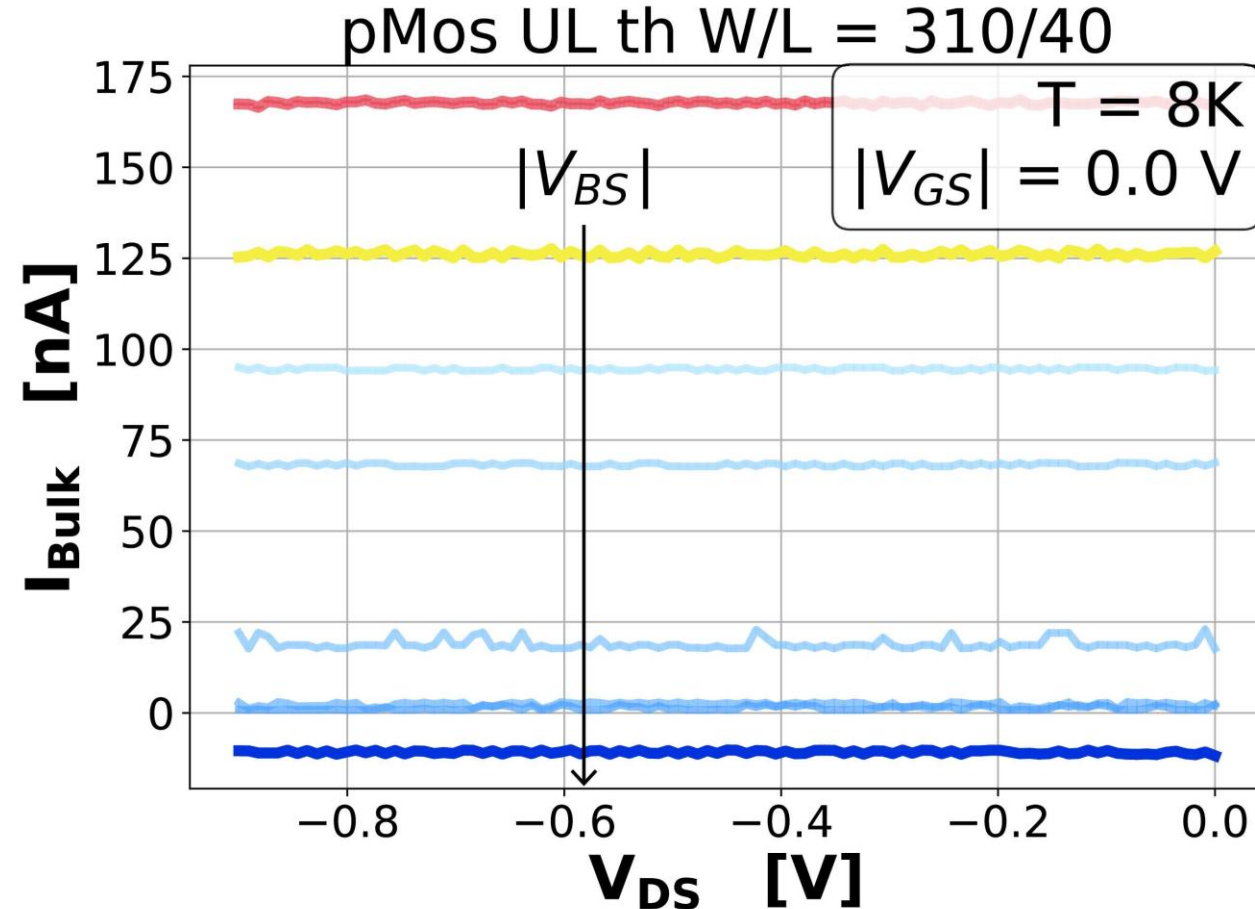
[1] TU Delft : Cryogenic-Aware Forward Body Biasing in Bulk CMOS, Overwater et al. 2024

# FORWARD BODY BIASING LIMITS AND LEAKAGES

Example UL threshold pMOS 310/40 @T=8K

T	$V_{SB,start}$	$V_{SB,stop}$	$V_{step}$
8K	0V	900mV	100mV
30K	0V	800mV	100mV
77K	0V	800mV	100mV

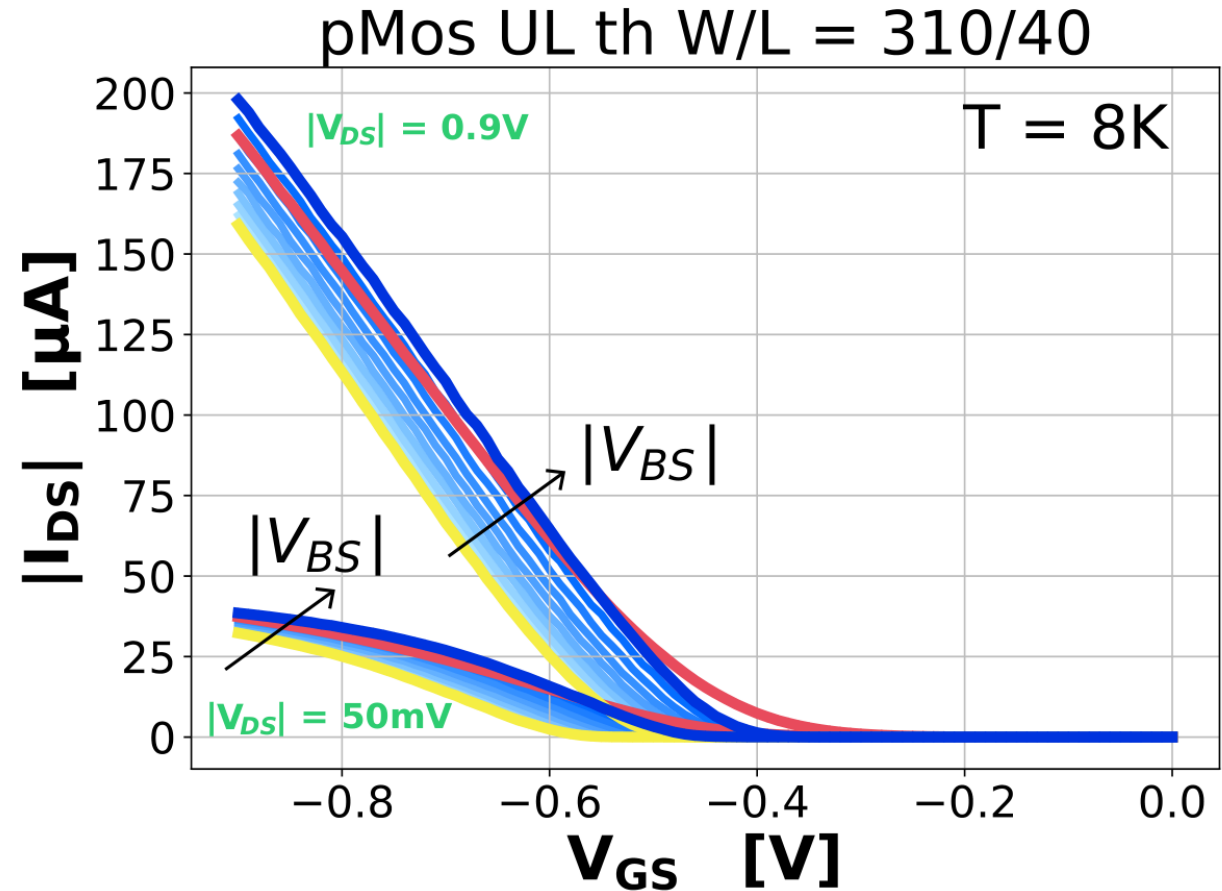
- All off/on leakages monitored,  $|V_{SB}|$  swept until S-B diode turned on (beyond tech limits at 8K)
- Significant **rev-leakage current reduction** → ulvt **more viable** (of interest because of lower  $V_{TH}$  and lower doping → less freeze-out impact)



# FORWARD BODY BIASING RESULTS

## Example UL threshold pMOS 310/40 @T=8K

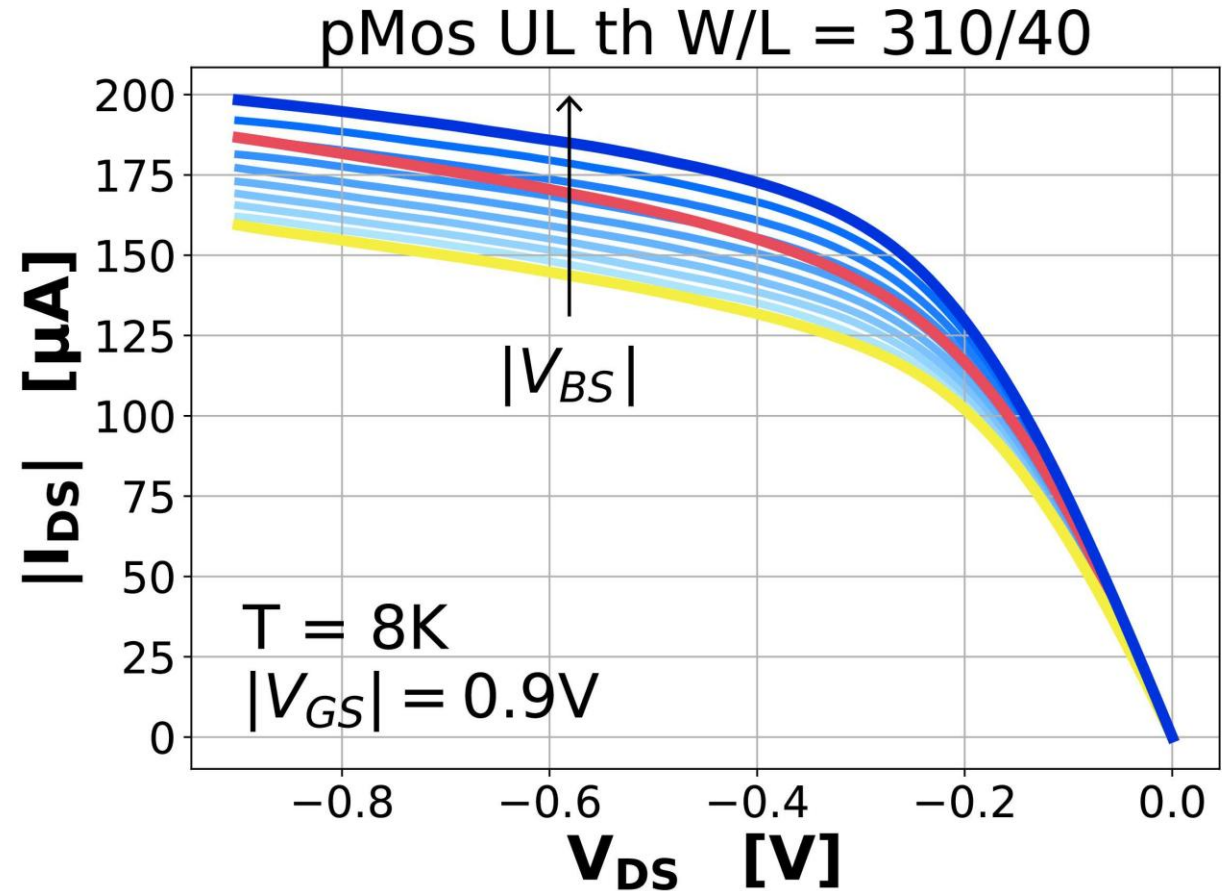
- Color legend:  $V_{SB} = 0V$ ,  $V_{SB} = 900mV$ ,  $V_{SB} \rightarrow$  increasing,  $V_{SB} = 0V$  and  $T = 300K$
- Transfer and strong inversion output characteristics shown, exhibiting threshold decrease and output current increase



# FORWARD BODY BIASING RESULTS

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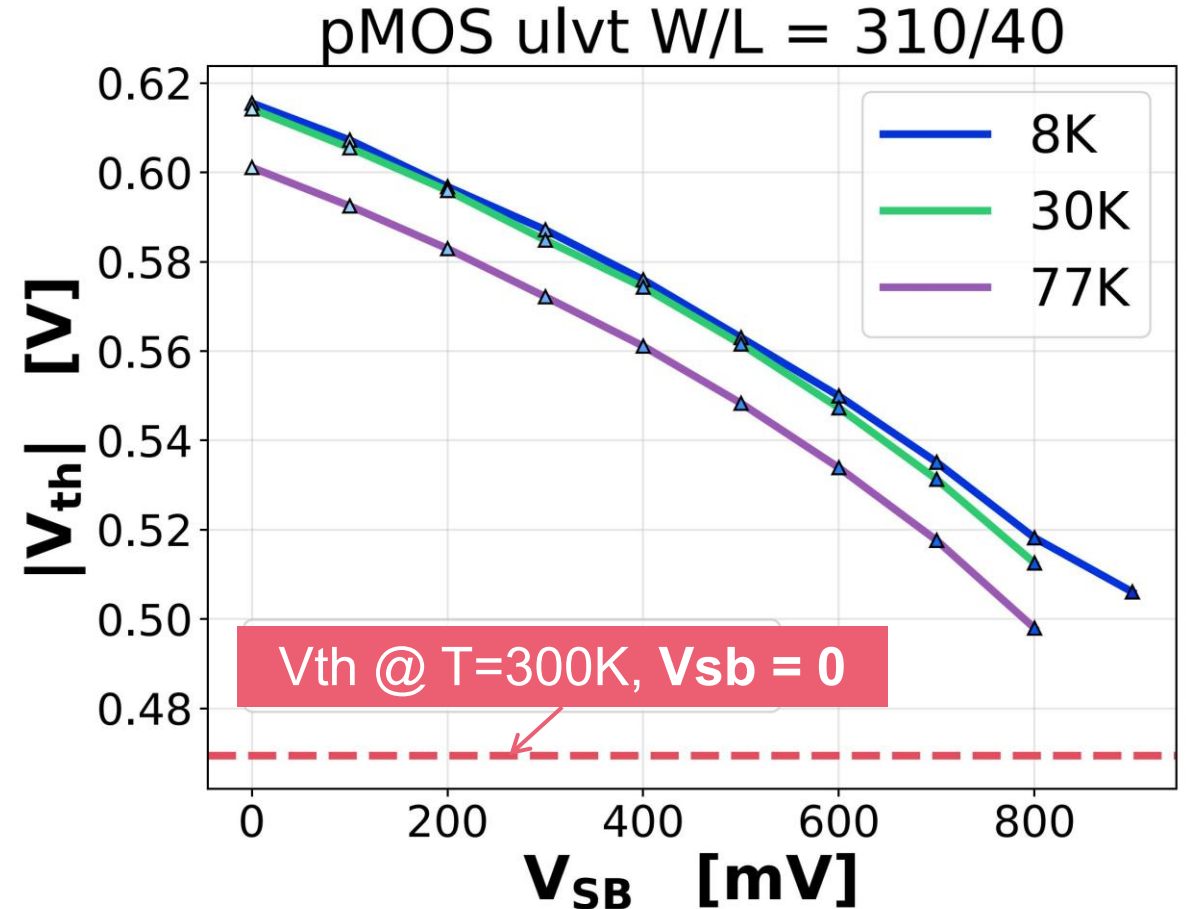
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# FORWARD BODY BIASING $V_{TH}$ TUNING

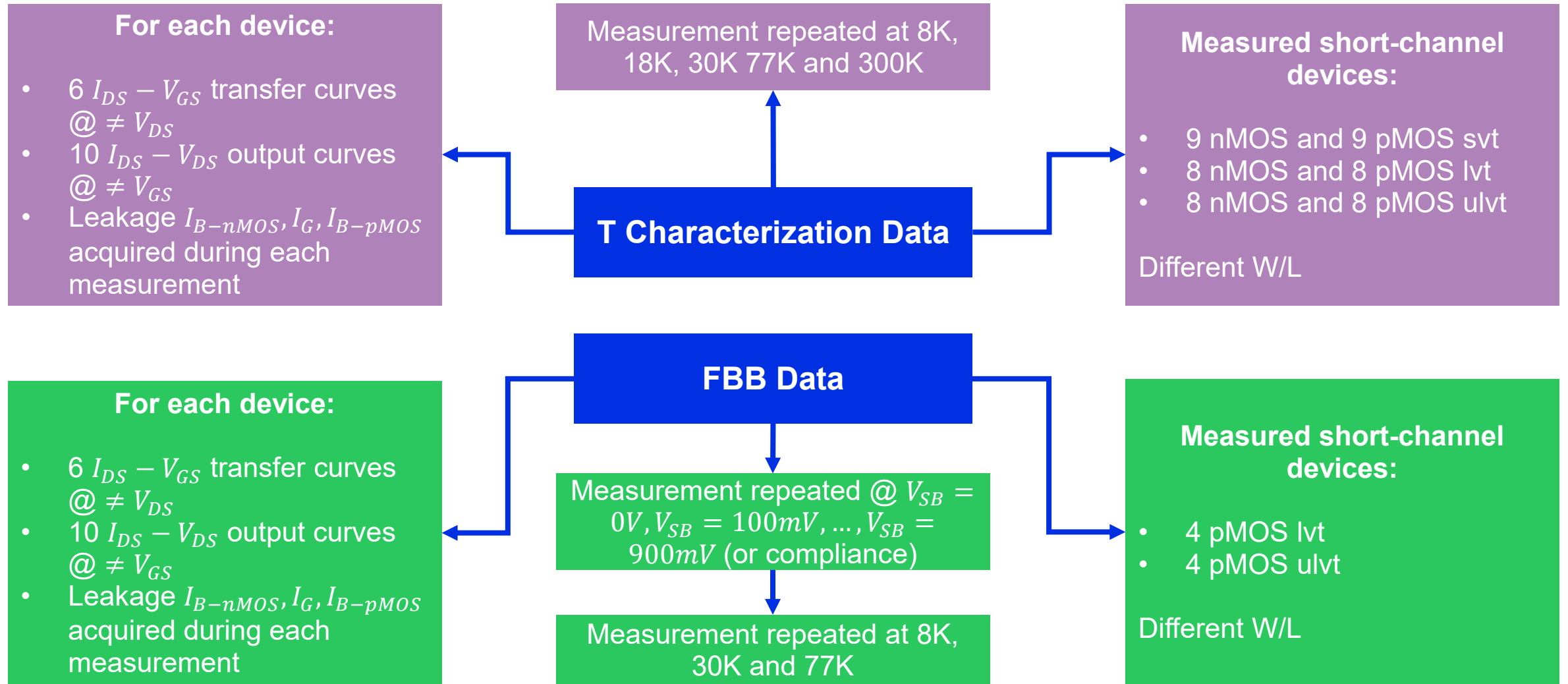
## Example UL threshold pMOS 310/40

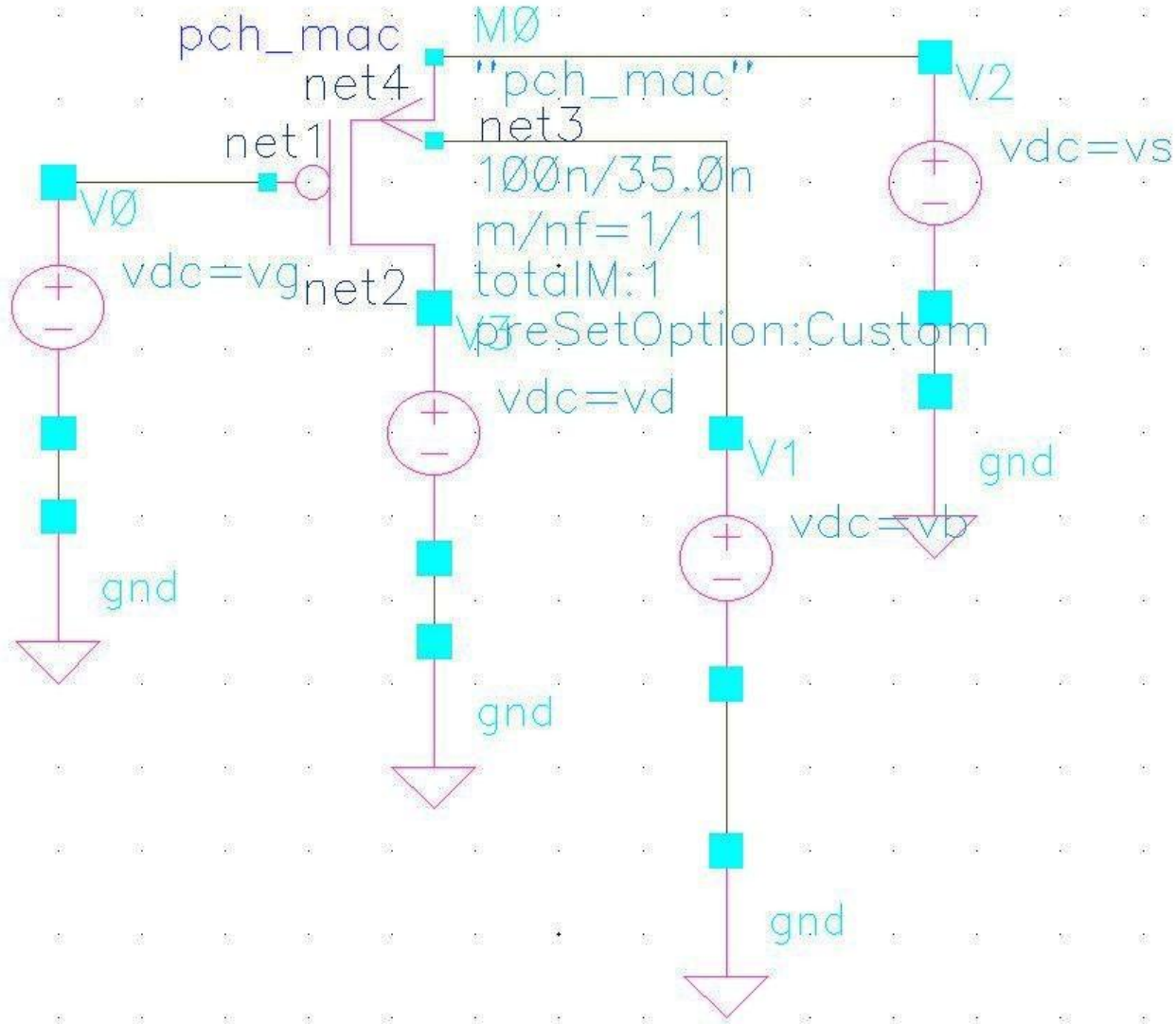
- $V_{th}$  with LE (Linear Extrapolation) Method [1]
- For no measured device  $V_{TH}$  reached room T level of operation
- A significant threshold voltage reduction of  $\sim 100mV$  is obtained, similarly at every temperature



[1] "Revisiting MOSFET threshold voltage extraction methods" Ortiz-Conde et al., 2013

# EXPERIMENTAL DATA – IN A NUTSHELL





# METHOD FOR CRYOGENIC CMOS MODEL EXTENSION

## INFN TORINO

# THE PARTIAL CRYO-PDK PROCEDURE

## Software Setup

### Goal: partial PDK

establish a **procedure** to create **cryo-corners** in 28-nm, valid at fixed thermal states

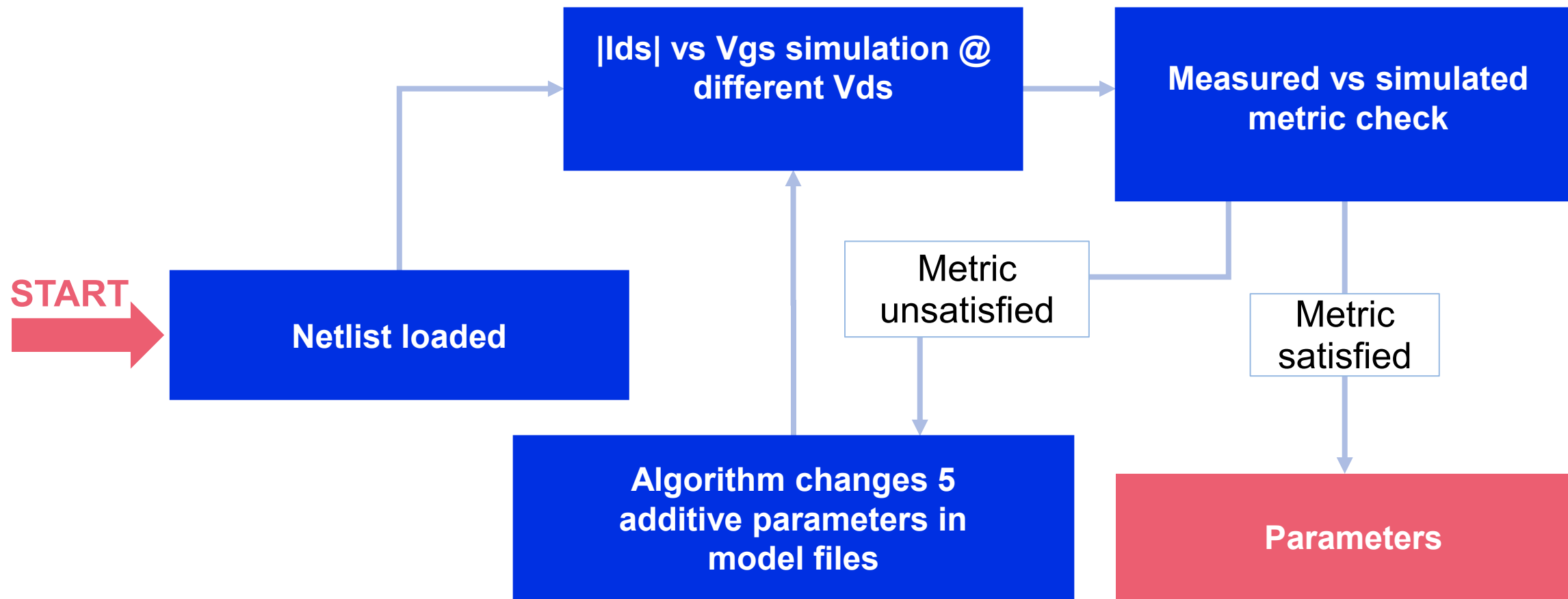
- SW Setup: Cadence Spectre + Python possible thanks to **pyspectre interface** <sup>[1]</sup>
- Model: **BSIM-BULK** (former BSIM-6) <sup>[2]</sup>
- Workspace was tested @ FZJ and setup @ INFN Torino
- 5 BSIM-BULK T dependent parameters chosen
- Additive components in custom model files →  $par = par_{28nm} + par_{CRYO}$
- Custom model files accessible via pyspectre

[1] "PySpectre: Python interface for Cadence Spectre" GitHub repository. Y. Uhlmann., Version 1.2.0. 2024

[2] "BSIM-BULK 107.2.1 MOSFET Compact Model". Berkeley, CA, 2025

# THE PARAMETER EXTRACTION PROCESS

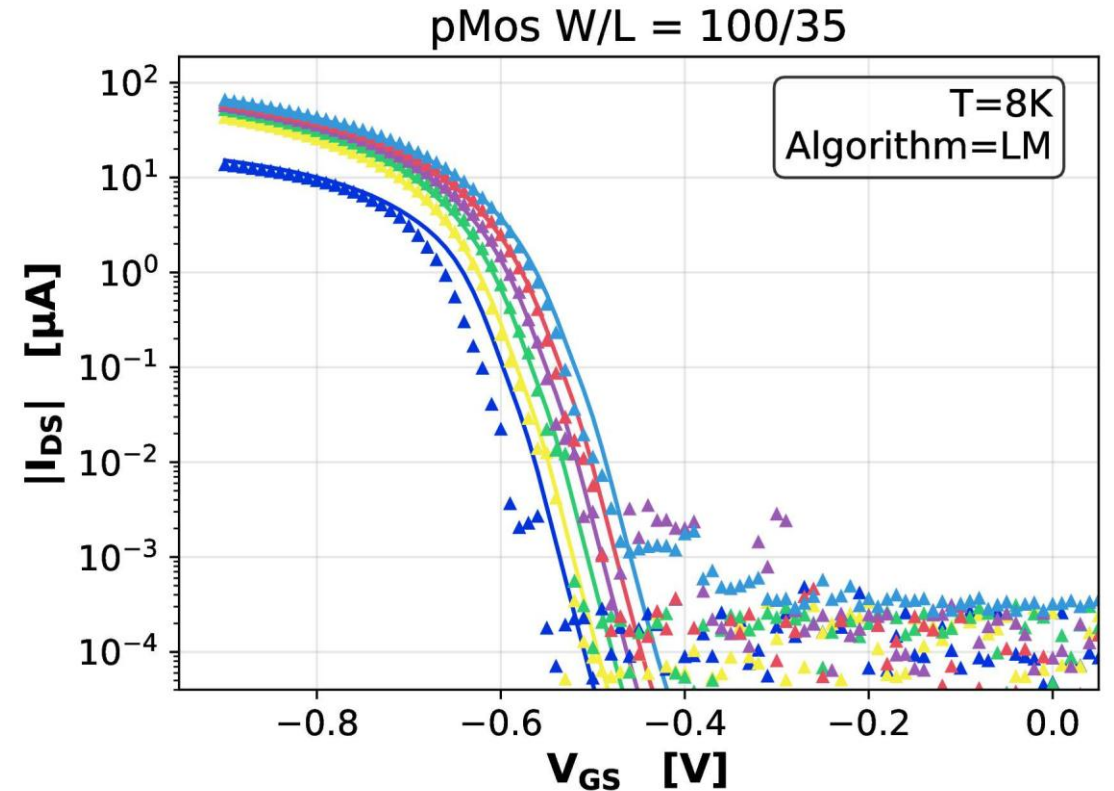
Pyspectre flow



# METRIC AND MULTIPLE FITTING ALGORITHM

svt pMOS W/L = 100/35

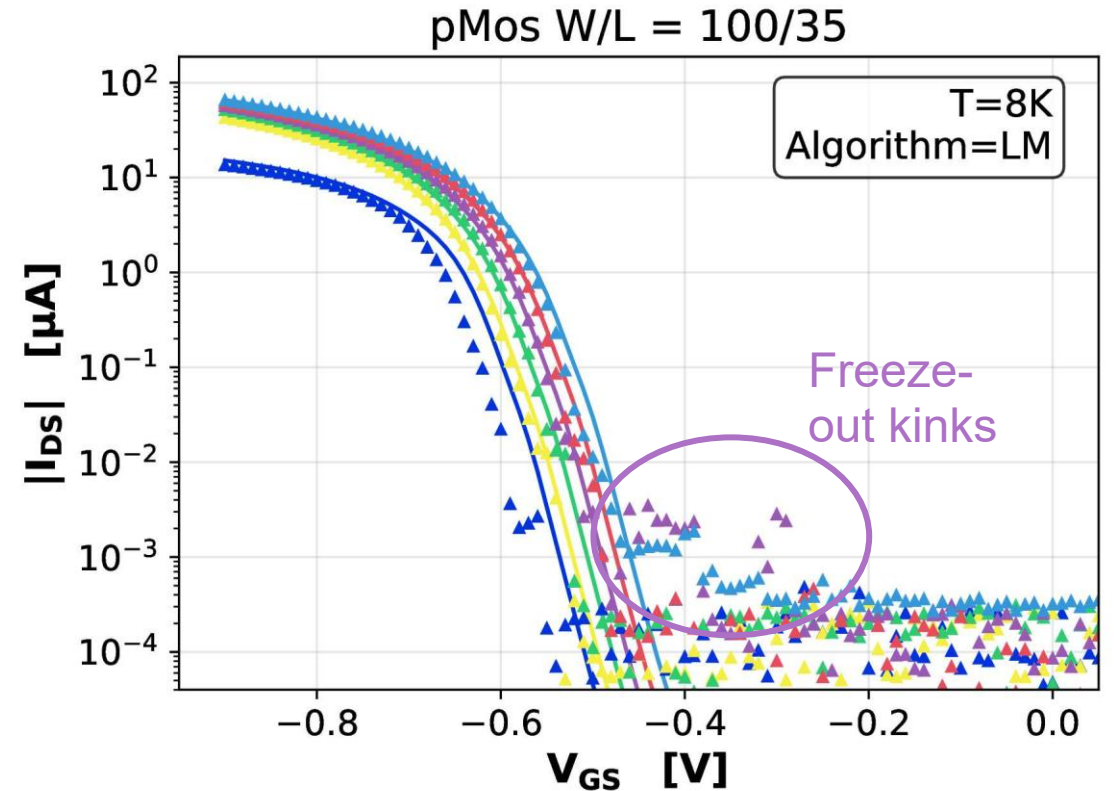
- Procedure tested on a single svt pMOS W/L = 100/35
- Chosen **metric** → mean square error sum [ $A^2$ ] with weightintg: moderate (50x) in strong inversion, heavy (150x) in sharp moderate inversion, light (0.5x) for sub-threshold noise
- **Algorithms** → two multidim tested: Levenberg-Marquardt and Nelder-Mead



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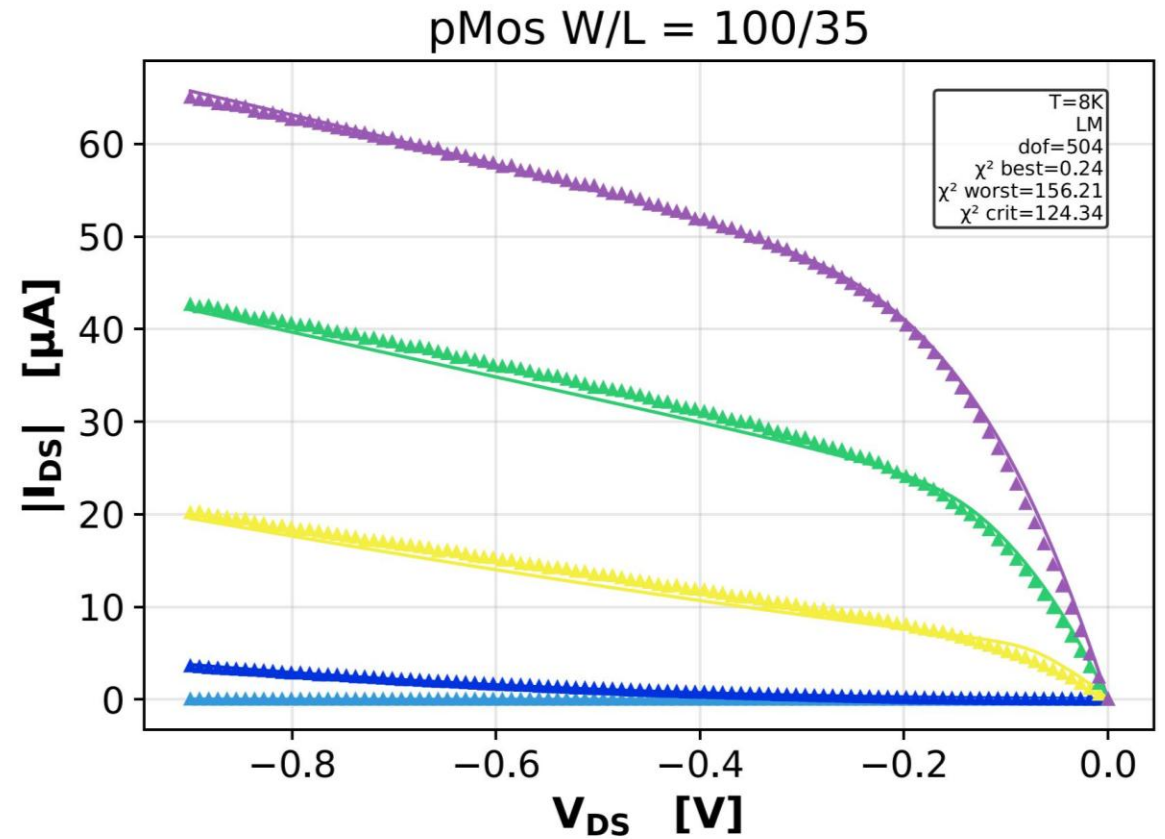
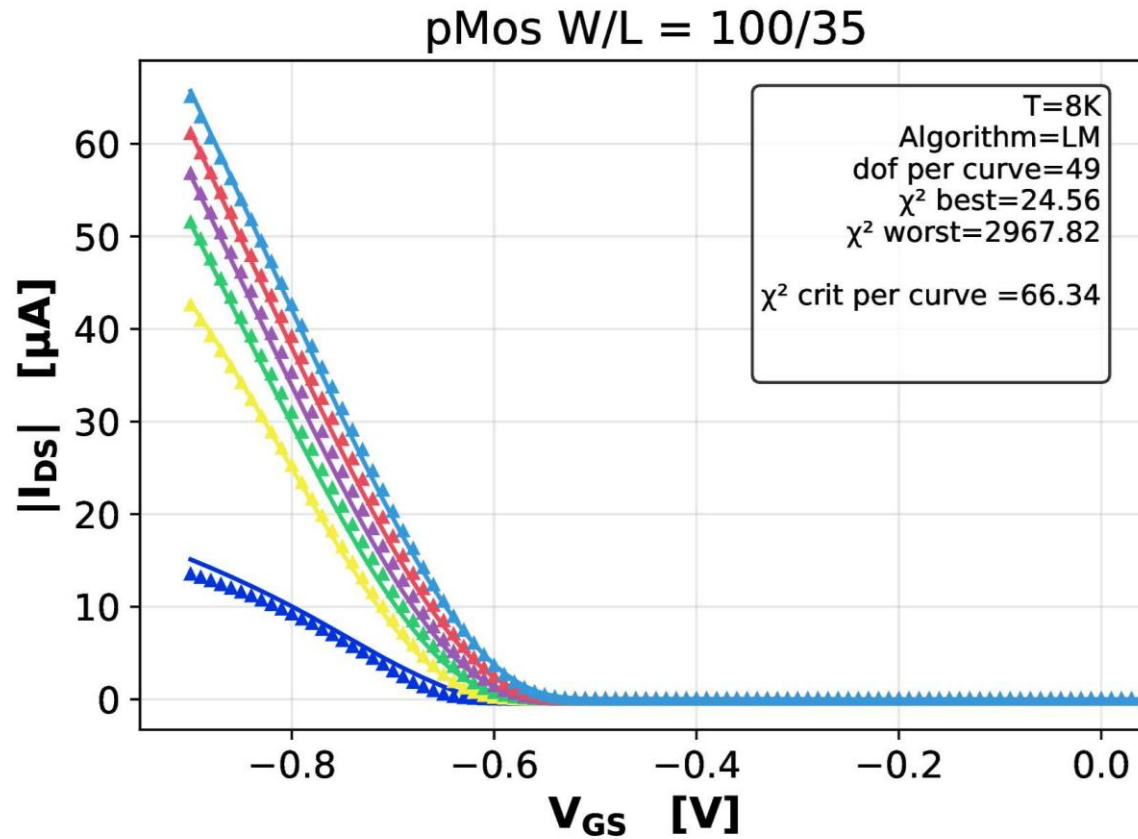
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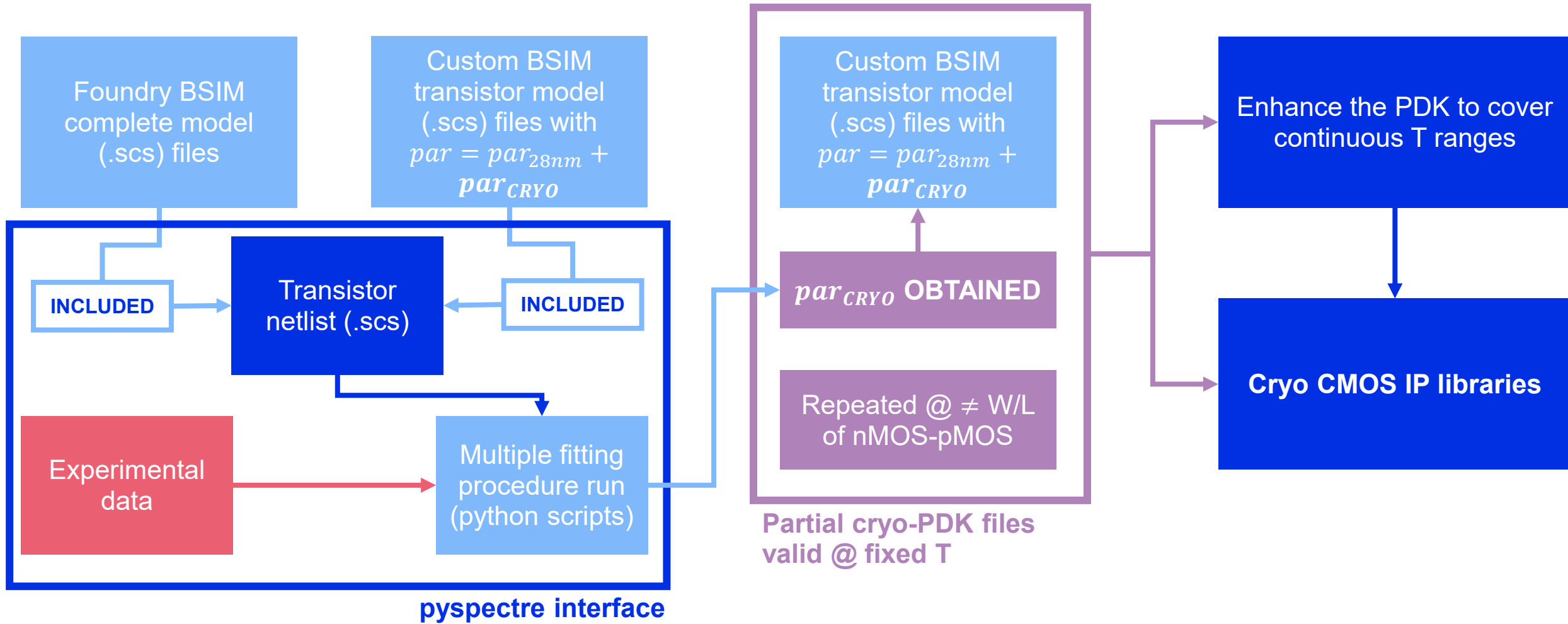


# SIM VS MEAS DATA – 8K

svt pMOS W/L = 100/35



# PARTIAL CRYO-PDK – IN A NUTSHELL



# CONCLUSIONS AND OUTLOOK

## Conclusions

- Collaborative research between UniTO, INFN and FZJ; 4 months on site at Julich for cryogenic data extraction.
- Implementation of a partial cryo-PDK for a 28-nm bulk CMOS technology, using experimental data at 8-18-30-77K and state-of-the-art methodology for a model extension at fixed temperatures.
- First test of the cyo-FBB technique (used for trimming the device  $V_{TH}$ ) on a bulk 28nm CMOS technology node.

## Outlook

- Development of a new cryogenic device model allowing for simulation over a continuous temperature range (instead of fixed thermal states), in collaboration with TU Graz (Austria).
- Design of a new DUT (bulk-28nm, other techs) optimised for cryogenic measurements – current measurement campaign used a DUT developed for radiation hardness studies.
- Design of a cryo-IP (bulk 28-nm) prototype using the partial PDK developed and available for the complete demonstration of the cryo-PDK.

# REFERENCES

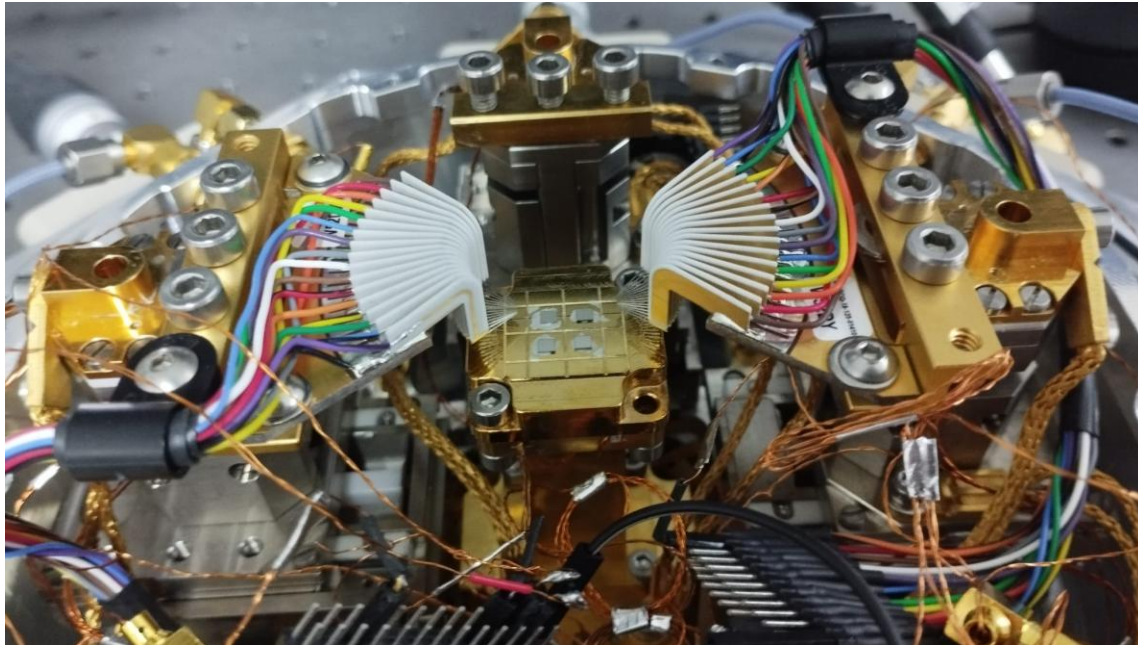
## Presentation references

- “DarkSide-20k sensitivity to light dark matter particles” Acerbi et al. 2024
- “Characterization and Modeling of 28 nm Bulk CMOS Technology down to 4.2K” Beckers et al., 2018
- “Revisiting MOSFET threshold voltage extraction methods” Ortiz-Conde et al., 2013
- “BSIM-BULK 107.2.1 MOSFET Compact Model”. Berkeley, CA, 2025.
- “PySpectre: Python interface for Cadence Spectre” GitHub repository. Y. Uhlmann., Version 1.2.0. 2024
- “Free Carrier Mobility Extraction in FETs”, F. Jazaeri et al., 2017
- “Characterization and modeling of 28-nm FDSOI CMOS technology down to cryogenic temperatures” Beckers et al. 2019
- “Cryogenic-Aware Forward Body Biasing in Bulk CMOS” Overwater et al. 2024

# BACKUP - DISCARDED SETUP

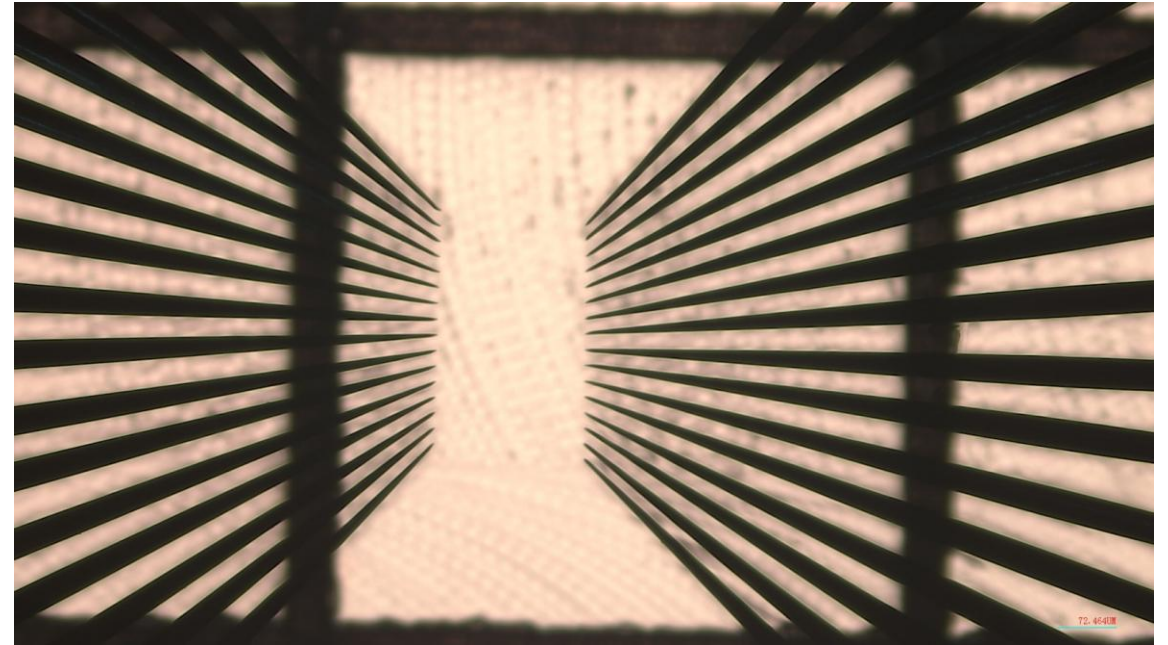
## 16L + 16R Needle Probes

- **TID** damage live monitoring:  
many devices contacted on the same cycle
- Contact @CERN: 2 entire columns sim. !!

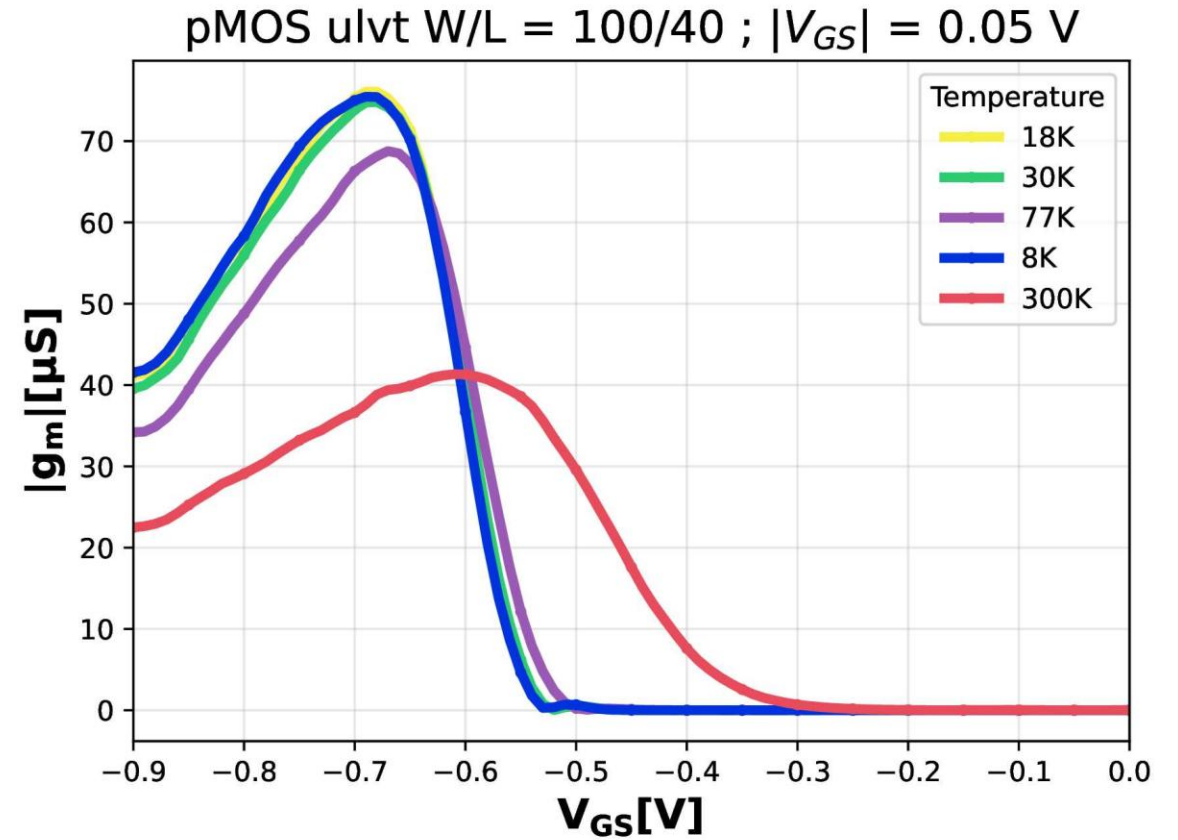
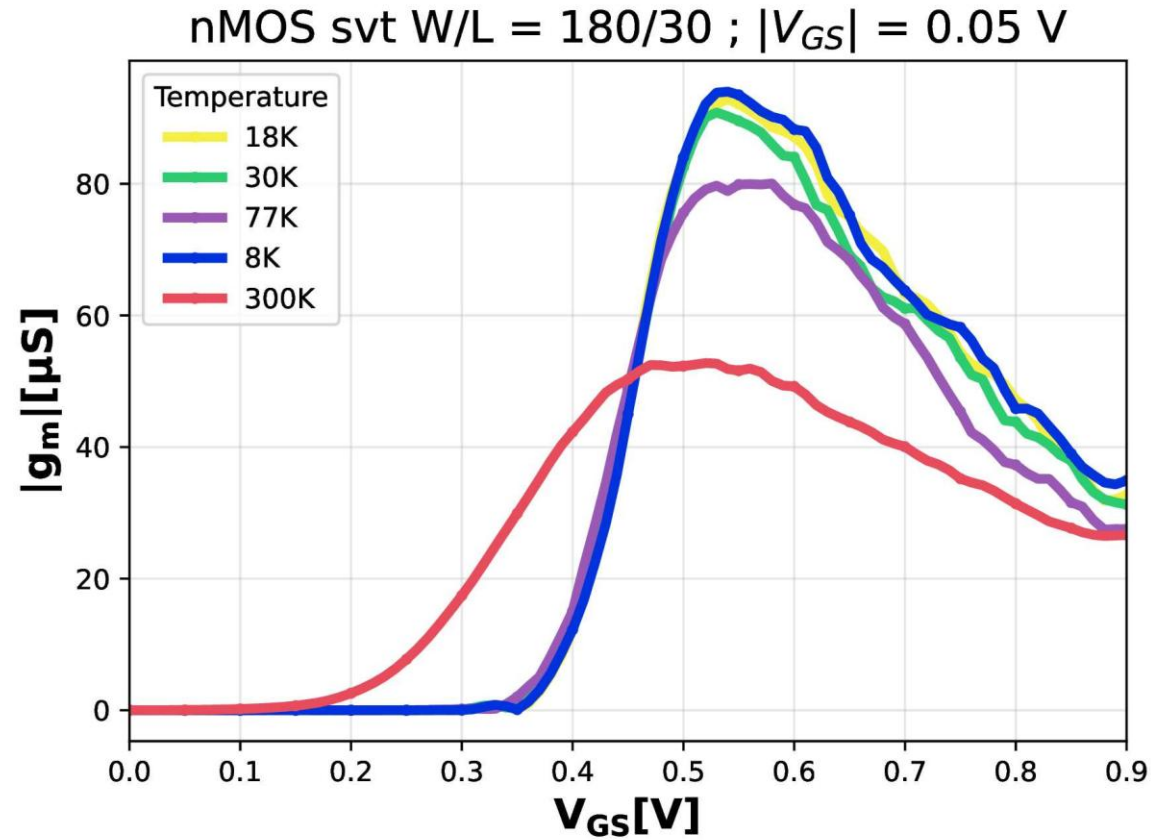


Tried but discarded:

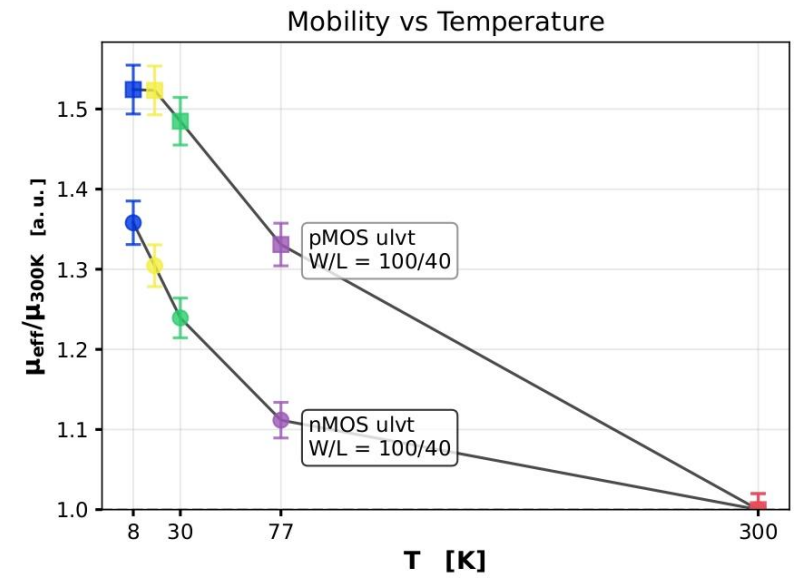
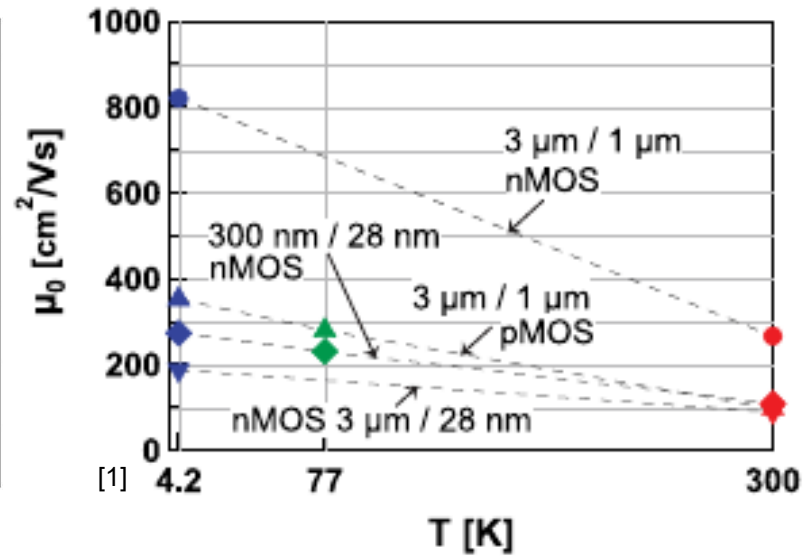
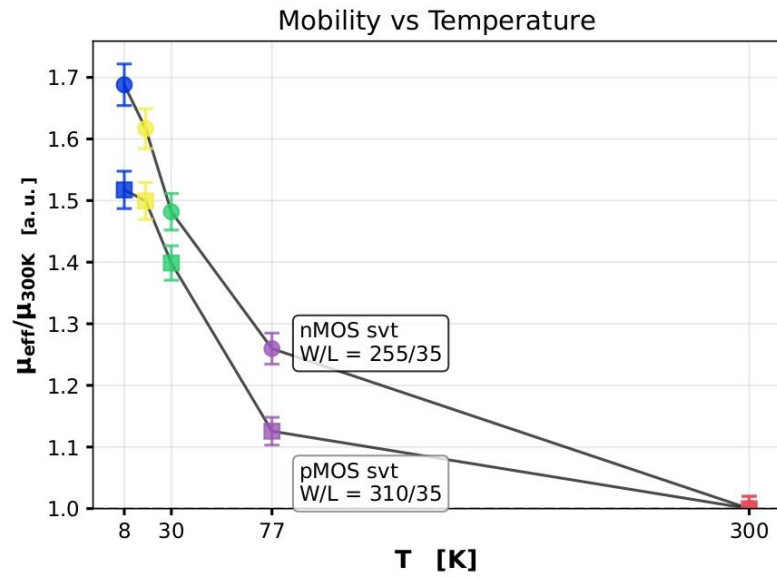
- Hard repeated contacts @cryo
- Vertical bending @cryo
- Lack of cryostat feedthroughs
- Heavy T load



# BACKUP - TRANSCONDUCTANCES



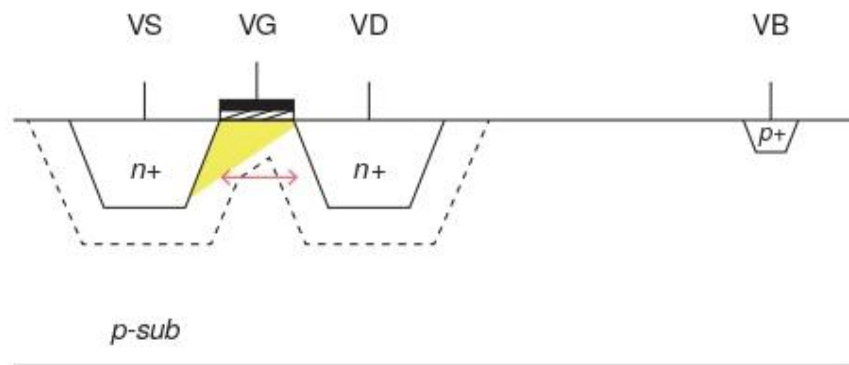
# BACKUP - MOBILITIES



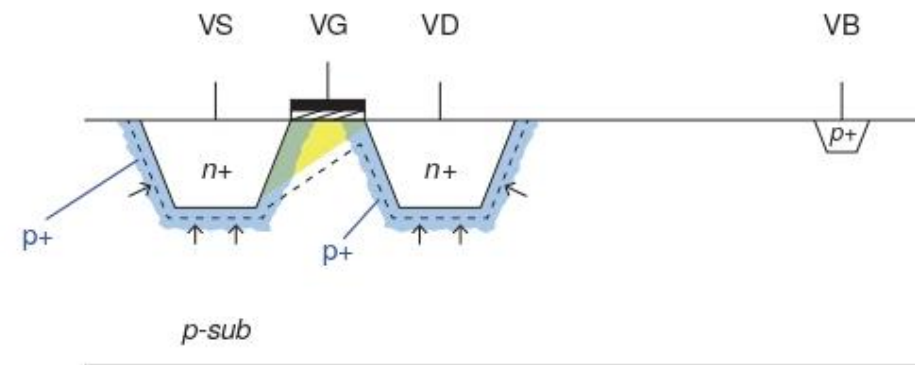
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# BACKUP – SHORT CHANNEL EFFECTS

## Drain-induced barrier lowering

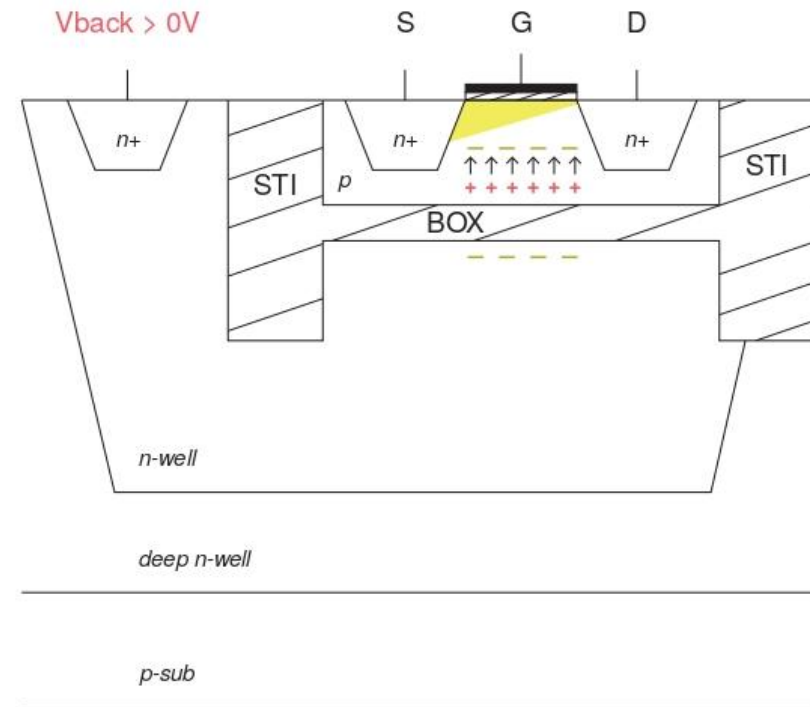
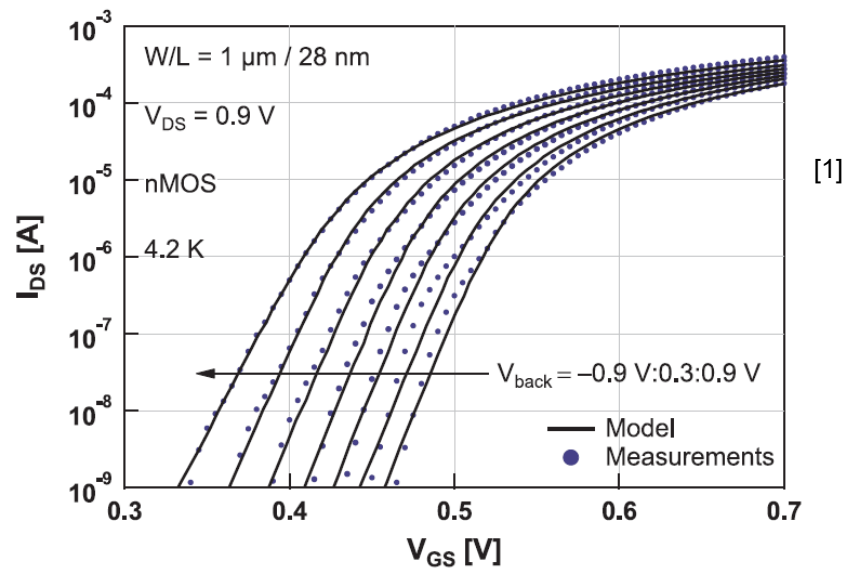


## Halo dopings



# BACKUP - FD-SOI BACKGATE TUNING OF $V_{th}$

- Increase of  $V_{th}$  in cryo
- Adjusted with  $V_{back}$
- One of the **advantages of SOI** for cryo ICs



[1] Characterization and modeling of 28-nm FDSOI CMOS technology down to cryogenic temperatures, Beckers et al. 2019

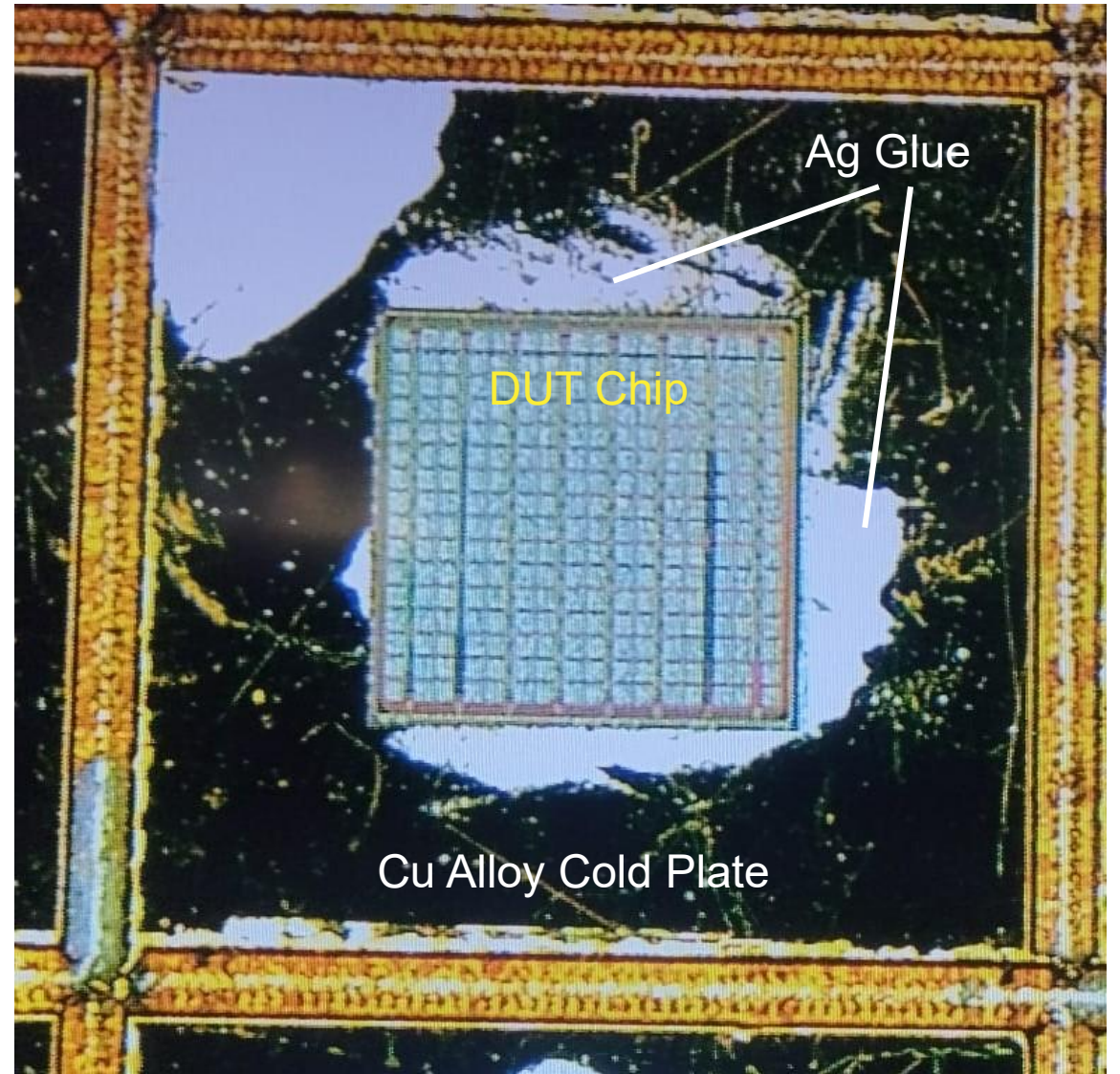
# BACKUP - PMOS FBB

- Only pMOS FBB because:

- Substrate in contact with the cold plate
- CERN Chip: no triple well nMOS devices



- $V_{B,nMOS}$  ↑ → Ground Loop
- $V_{S,nMOS}$  ↓ →  $V_S < V_{SS}$  -> ESD Diode on S



# BACKUP – STATYSTICAL TESTING

svt pMOS W/L = 100/35, Levenberg Marquardt algorithm

$\chi^2$	$V_D$ (V)
$3.64 \cdot 10^2$	<b>0.85</b>
$6.64 \cdot 10^0$	<b>0.68</b>
$1.88 \cdot 10^1$	<b>0.51</b>
$1.60 \cdot 10^1$	<b>0.34</b>
$8.73 \cdot 10^0$	<b>0.17</b>
$1.41 \cdot 10^1$	<b>0.0</b>
$\chi_{crit}^2$	$6.64 \cdot 10^1$

Table 4.13:  $I_{DS} - V_{GS}$  chi squares at 8 K.

- $\sigma = \max\{10\% \cdot I_{DS}, 0.1 \mu A\}$

$\chi^2$	$V_G$ (V)
$1.98 \cdot 10^1$	<b>0.0</b>
$2.07 \cdot 10^1$	<b>0.1</b>
$1.56 \cdot 10^2$	<b>0.2</b>
$3.04 \cdot 10^1$	<b>0.3</b>
$2.36 \cdot 10^{-1}$	<b>0.4</b>
$\chi_{crit}^2$	$1.24 \cdot 10^2$

Table 4.14:  $I_{DS} - V_{DS}$  chi squares at 8 K.

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Table 4.13:  $I_{DS} - V_{GS}$  chi squares at 8 K.

$\chi^2$	$V_G$ (V)
$1.98 \cdot 10^1$	0.0
$2.07 \cdot 10^1$	0.1
$1.56 \cdot 10^2$	0.2
$3.04 \cdot 10^1$	0.3
$2.36 \cdot 10^{-1}$	0.4
$\chi_{crit}^2$	$1.24 \cdot 10^2$

Table 4.14:  $I_{DS} - V_{DS}$  chi squares at 8 K.

- $\sigma = \max\{10\% \cdot I_{DS}, 0.1 \mu A\}$
- $\chi^2$  not passed  $\rightarrow$  model extension weakness in linear region

# BACKUP – STATYSTICAL TESTING

svt pMOS W/L = 100/35, Levenberg Marquardt algorithm

$\chi^2$	$V_D$ (V)
$3.64 \cdot 10^2$	<b>0.85</b>
$6.64 \cdot 10^0$	<b>0.68</b>
$1.88 \cdot 10^1$	<b>0.51</b>
$1.60 \cdot 10^1$	<b>0.34</b>
$8.73 \cdot 10^0$	<b>0.17</b>
$1.41 \cdot 10^1$	<b>0.0</b>
$\chi_{crit}^2$	$6.64 \cdot 10^1$

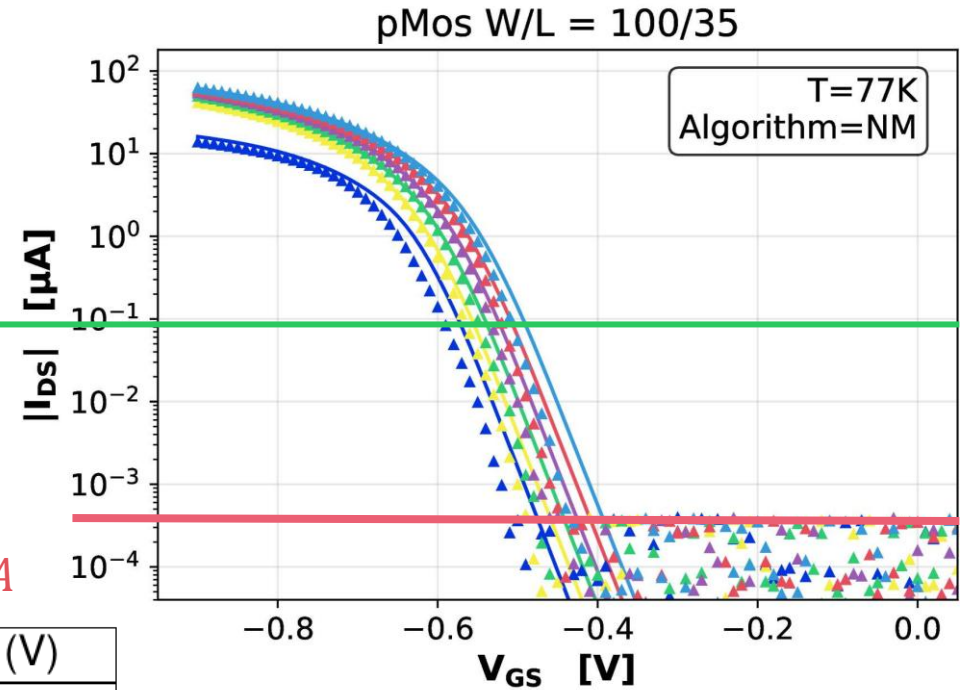
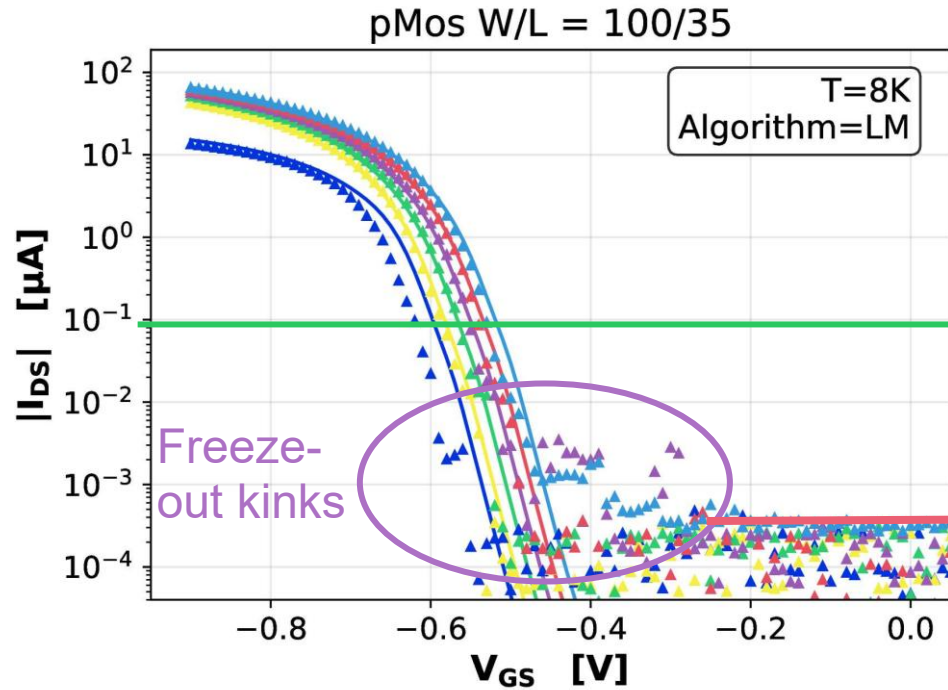
Table 4.13:  $I_{DS} - V_{GS}$  chi squares at 8 K.

- $\sigma = \max\{10\% \cdot I_{DS}, 0.1 \mu A\}$
- $\chi^2$  **passed**, or barely **not** (low  $|V_{DS}|$  regime)

$\chi^2$	$V_G$ (V)
$1.98 \cdot 10^1$	<b>0.0</b>
$2.07 \cdot 10^1$	<b>0.1</b>
$1.56 \cdot 10^2$	<b>0.2</b>
$3.04 \cdot 10^1$	<b>0.3</b>
$2.36 \cdot 10^{-1}$	<b>0.4</b>
$\chi_{crit}^2$	$1.24 \cdot 10^2$

Table 4.14:  $I_{DS} - V_{DS}$  chi squares at 8 K.

# BACKUP – STATYSTICAL TESTING



Max noise levels  
 $\sim 3 \cdot 10^{-10} A$

$\chi^2$	$V_D$ (V)
$1.11 \cdot 10^4$	0.85
$1.42 \cdot 10^2$	0.28
$9.87 \cdot 10^1$	0.51
$2.24 \cdot 10^2$	0.34
$5.66 \cdot 10^2$	0.17
$1.26 \cdot 10^3$	0.0
$\chi_{crit}^2$	$6.64 \cdot 10^1$

# BACKUP - ALGORITHMS COMPARISON

8K optimization 5 parameters

- Same initial guess, same 5 pars
- Same target RMS → adherence sim-meas

## Levenberg-Marquardt

- Total time: **30.43 s**
- Function evals: 29
- Time per eval: 1.05 s
- Final cost:  $9.4e-07 A^2$
- Final RMS:  $3.5e-05 A$
- Quadratic

**Faster** but **more sensitive** to loc. min. and initial guess

## Nelder-Mead

- Total time: **113.50 s**
- Function evals: 149
- Time per eval: 0.46 s
- Final cost:  $9.4e-07 A^2$
- Final RMS:  $3.5e-05 A$
- Linear

**Less sensitive** to loc. min. and initial guess but **slower**